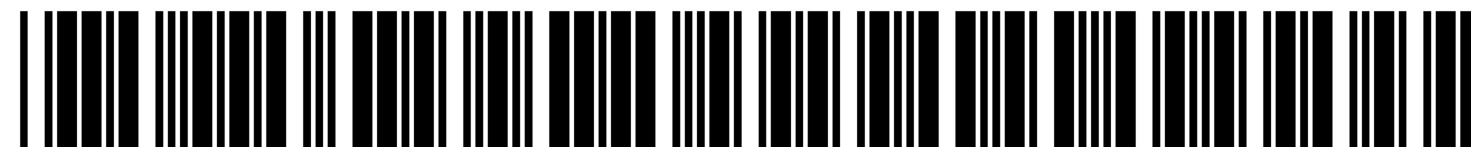

(12) **United States Patent**
Zhang

(10) **Patent No.: US 10,388,659 B2**
(45) **Date of Patent: Aug. 20, 2019**

(54) **VERTICAL GATE-ALL-AROUND TFET**

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(72) Inventor: **John H. Zhang**, Altamont, NY (US)

(73) Assignee: **STMICROELECTRONICS, INC.**, Coppell, TX (US)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

(21) Appl. No.: **15/939,108**

(22) Filed: **Mar. 28, 2018**

(65) **Prior Publication Data**

US 2018/0286869 A1 Oct. 4, 2018

Related U.S. Application Data

(60) Continuation of application No. 15/482,610, filed on Apr. 7, 2017, now Pat. No. 9,953,983, which is a

(Continued)

(51) **Int. Cl.**

H01L 21/00 (2006.01)
H01L 21/8238 (2006.01)

(Continued)

(52) **U.S. Cl.**

CPC ***H01L 27/10879*** (2013.01); ***B82Y 10/00*** (2013.01); ***H01L 21/28008*** (2013.01); ***H01L 21/823814*** (2013.01); ***H01L 21/823871*** (2013.01); ***H01L 21/823885*** (2013.01); ***H01L 21/823892*** (2013.01); ***H01L 27/0814*** (2013.01); ***H01L 27/092*** (2013.01); ***H01L 27/0928*** (2013.01); ***H01L 29/0653*** (2013.01); ***H01L 29/0676*** (2013.01); ***H01L 29/1033*** (2013.01);

(Continued)

(58) **Field of Classification Search**

CPC H01L 29/78642; H01L 29/78618; H01L 29/78696; H01L 29/66666; H01L 29/66909; H01L 29/66795; H01L 29/7827; H01L 29/1041; H01L 21/823892; H01L 21/823821

See application file for complete search history.

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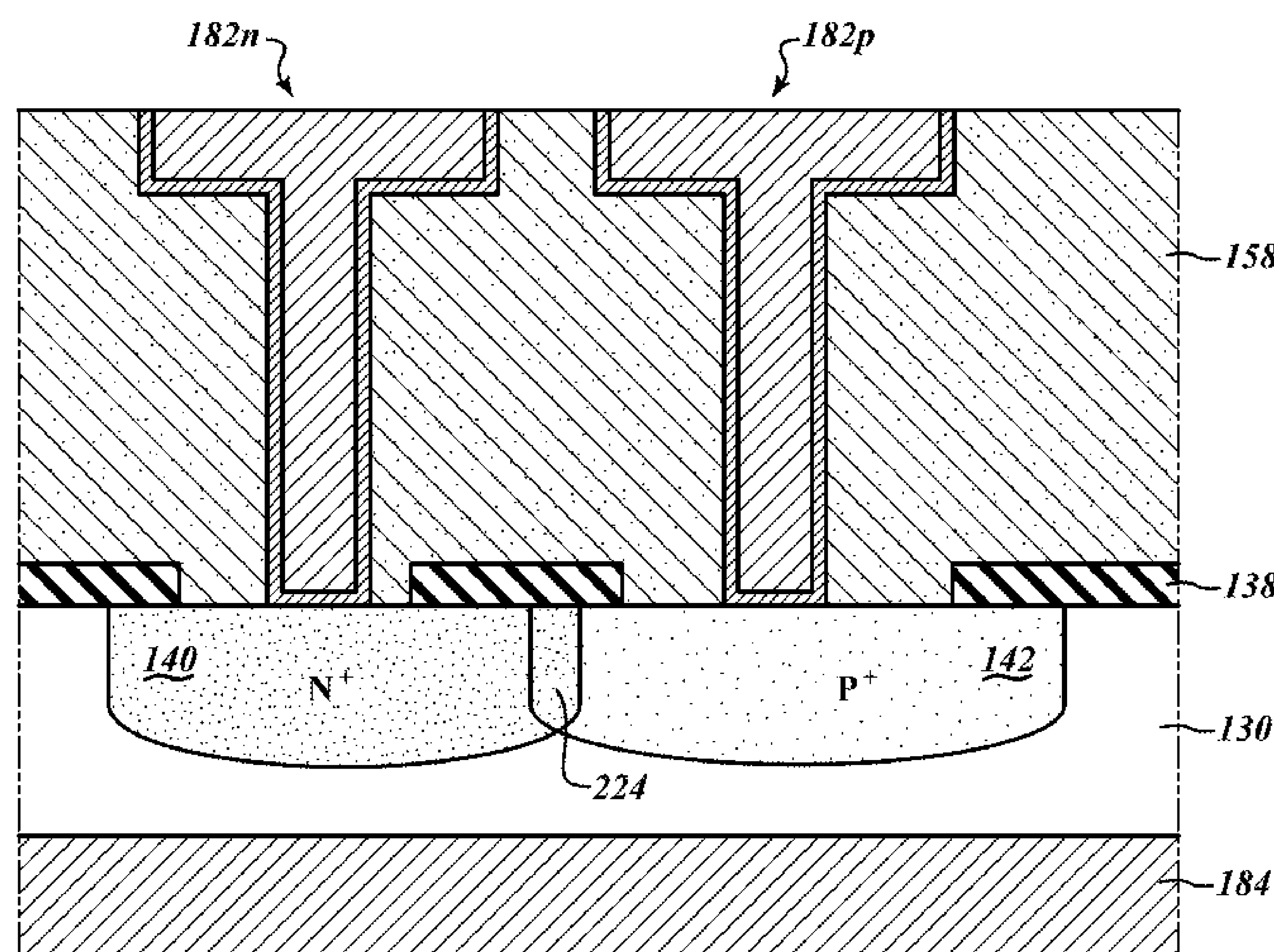
(74) *Attorney, Agent, or Firm* — Seed IP Law Group LLP

(57) **ABSTRACT**

A vertical tunneling FET (TFET) provides low-power, high-speed switching performance for transistors having critical dimensions below 7 nm. The vertical TFET uses a gate-all-around (GAA) device architecture having a cylindrical structure that extends above the surface of a doped well formed in a silicon substrate. The cylindrical structure includes a lower drain region, a channel, and an upper source region, which are grown epitaxially from the doped well. The channel is made of intrinsic silicon, while the source and drain regions are doped in-situ. An annular gate surrounds the channel, capacitively controlling current flow through the channel from all sides. The source is electrically accessible via a front side contact, while the drain is accessed via a backside contact that provides low contact resistance and also serves as a heat sink. Reliability of vertical TFET integrated circuits is enhanced by coupling the vertical TFETs to electrostatic discharge (ESD) diodes.

16 Claims, 13 Drawing Sheets



Related U.S. Application Data

continuation of application No. 15/177,231, filed on Jun. 8, 2016, now Pat. No. 9,653,585, which is a division of application No. 14/675,536, filed on Mar. 31, 2015, now Pat. No. 9,385,195.

(51) **Int. Cl.**

H01L 27/108	(2006.01)
H01L 29/06	(2006.01)
H01L 29/16	(2006.01)
H01L 29/78	(2006.01)
H01L 29/20	(2006.01)
H01L 29/66	(2006.01)
H01L 21/28	(2006.01)
H01L 27/092	(2006.01)
H01L 29/423	(2006.01)
H01L 29/786	(2006.01)
H01L 29/10	(2006.01)
B82Y 10/00	(2011.01)
H01L 29/775	(2006.01)
H01L 27/08	(2006.01)
H01L 31/0392	(2006.01)
H01L 33/04	(2010.01)
H01L 45/00	(2006.01)
H01L 29/739	(2006.01)
H01L 29/49	(2006.01)

(52) **U.S. Cl.**

CPC ***H01L 29/16*** (2013.01); ***H01L 29/20*** (2013.01); ***H01L 29/42392*** (2013.01); ***H01L 29/66439*** (2013.01); ***H01L 29/66666*** (2013.01); ***H01L 29/66795*** (2013.01); ***H01L 29/66909*** (2013.01); ***H01L 29/66977*** (2013.01); ***H01L 29/7391*** (2013.01); ***H01L 29/775*** (2013.01); ***H01L 29/7827*** (2013.01); ***H01L 29/7855*** (2013.01); ***H01L 29/7856*** (2013.01); ***H01L 29/78618*** (2013.01); ***H01L 29/78642*** (2013.01); ***H01L 29/78696*** (2013.01); ***H01L 31/0392*** (2013.01); ***H01L 33/04*** (2013.01); ***H01L 45/1233*** (2013.01); *H01L 21/823807* (2013.01); *H01L 21/823828* (2013.01); *H01L 21/823878* (2013.01); *H01L 29/495* (2013.01); *H01L 29/4966* (2013.01); *H01L 2029/7858* (2013.01)

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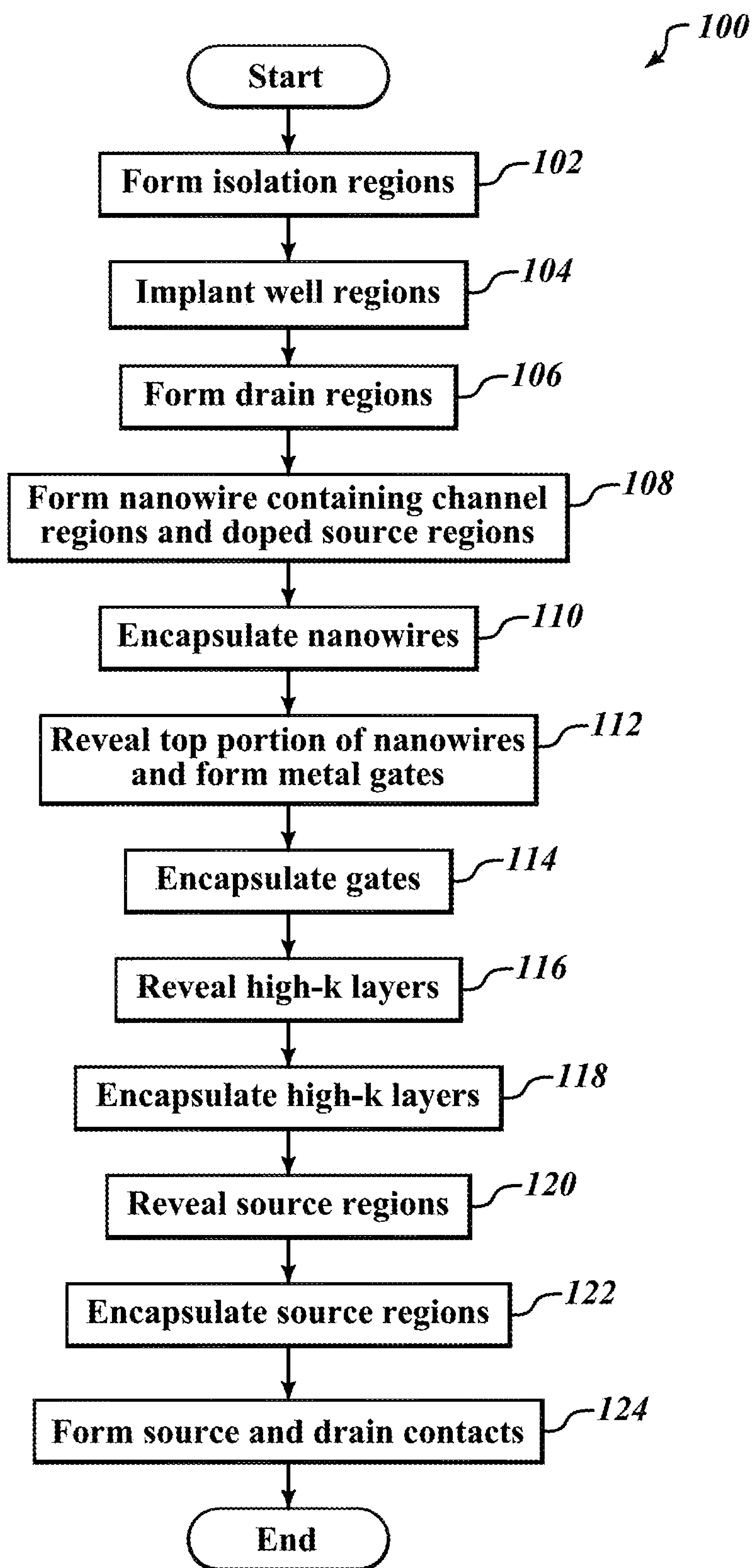

FIG. 1

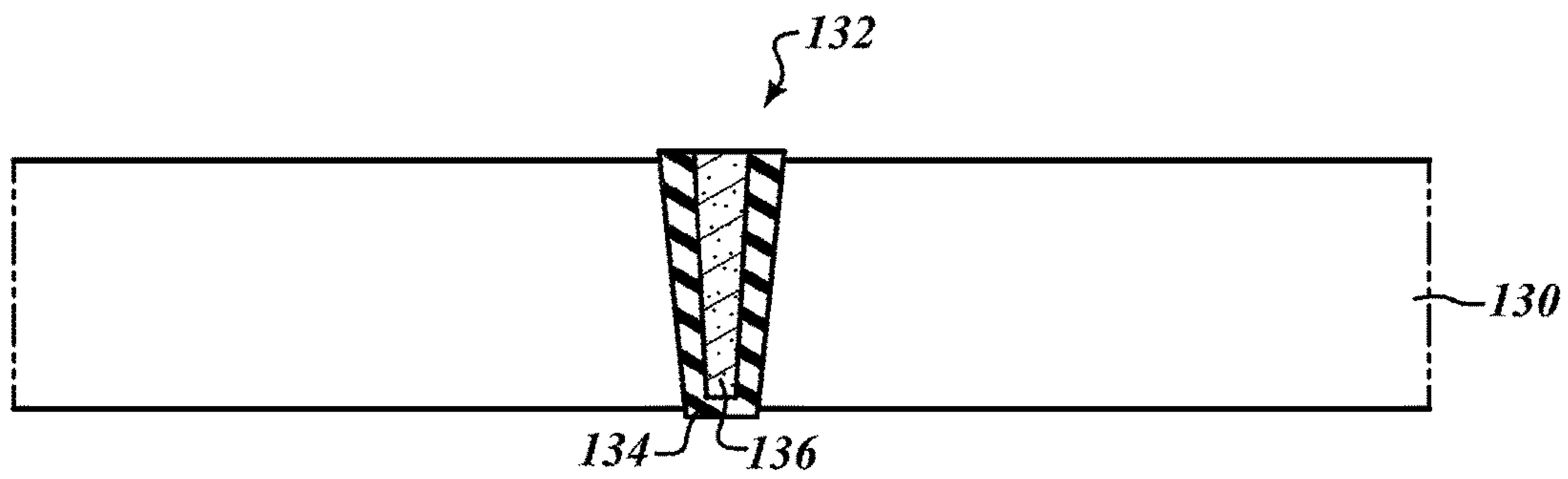

FIG.2

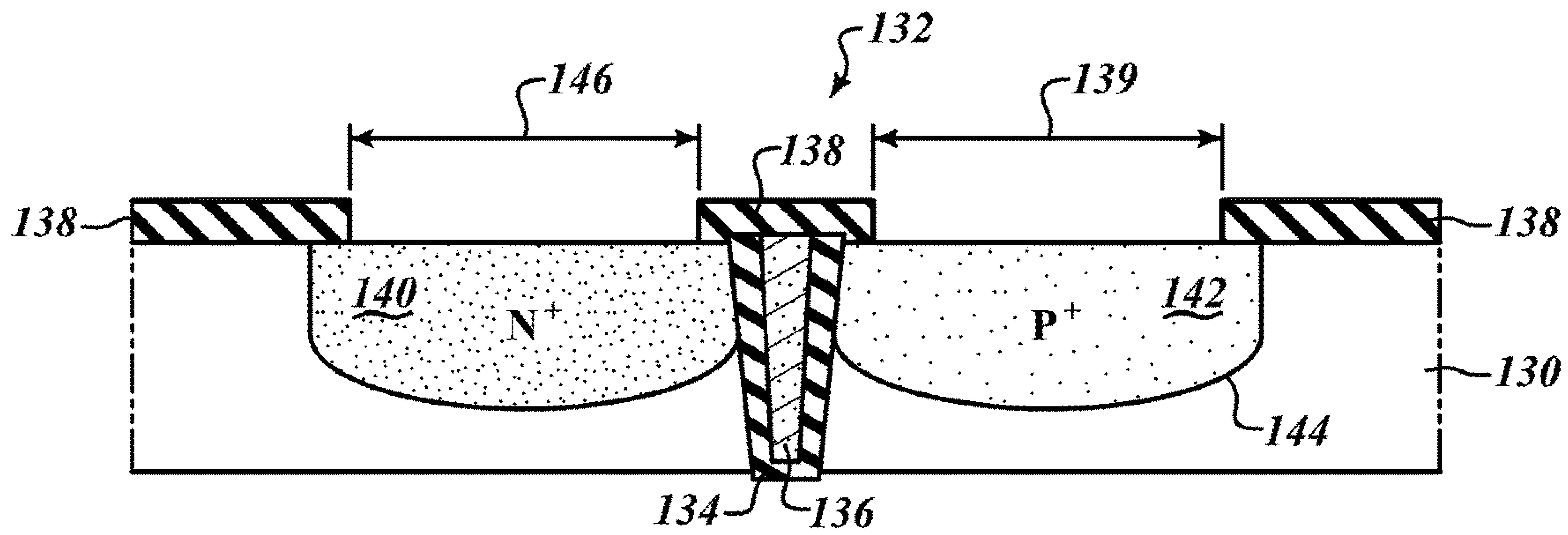

FIG.3

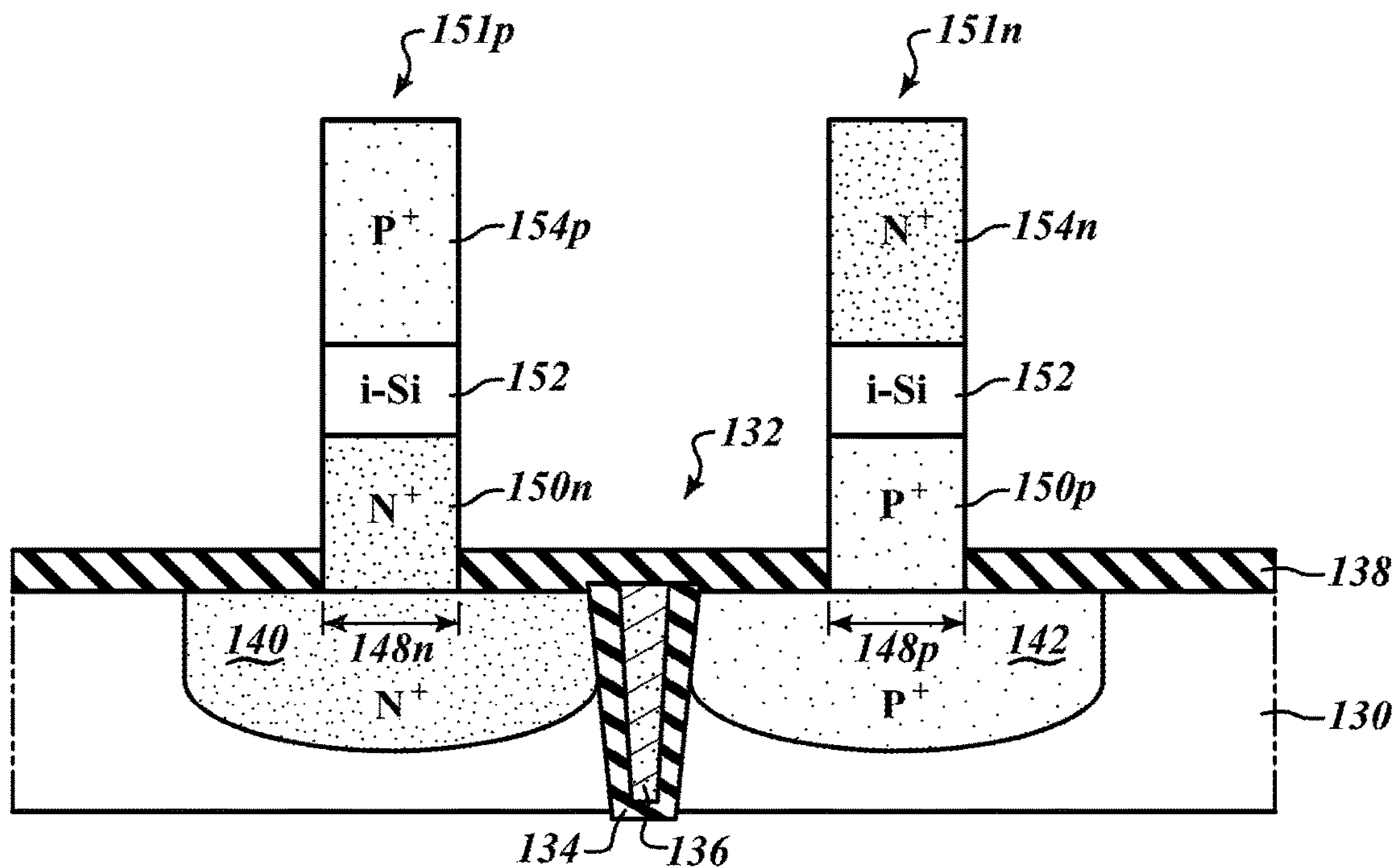

FIG. 4

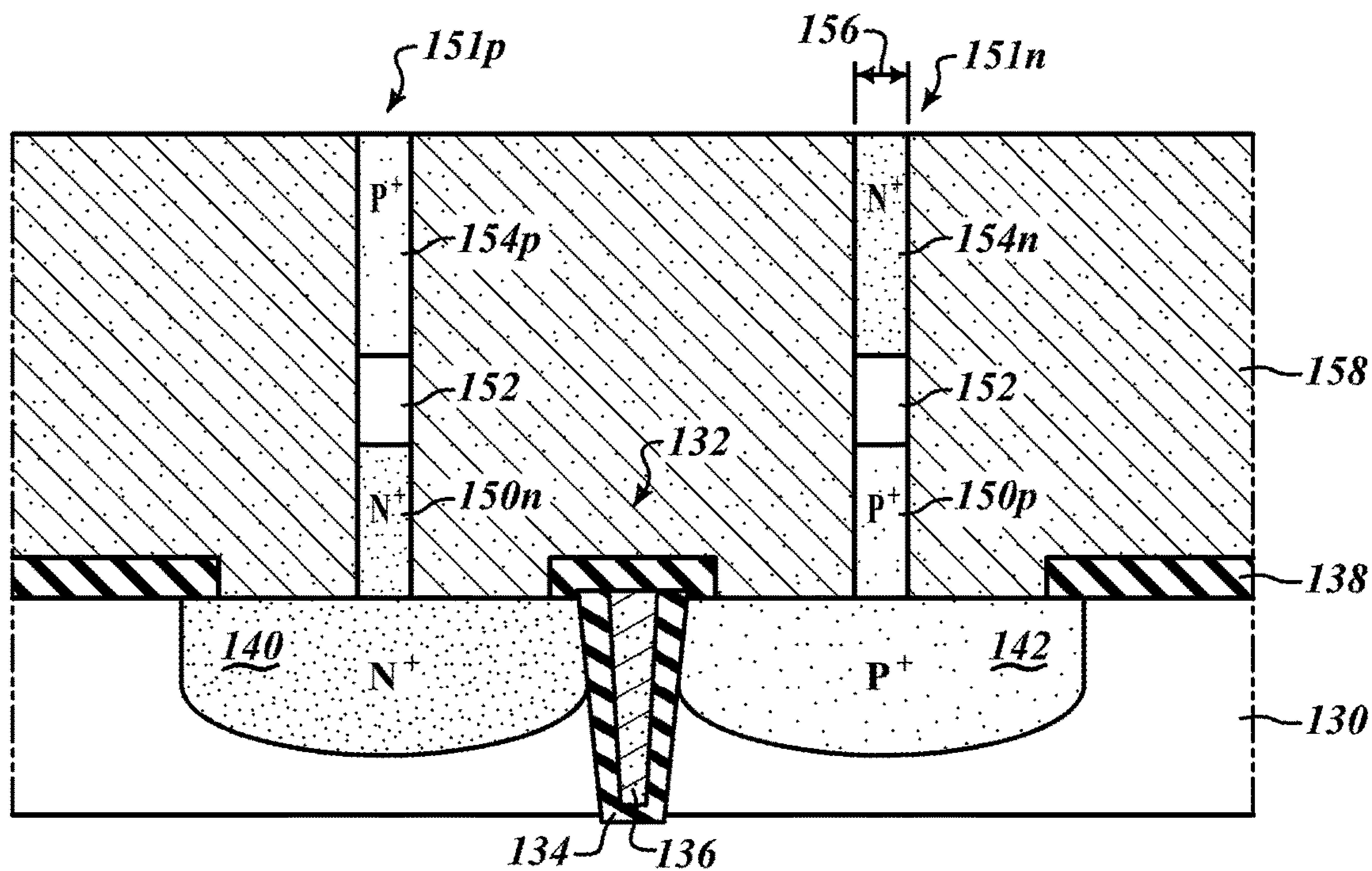

FIG. 5

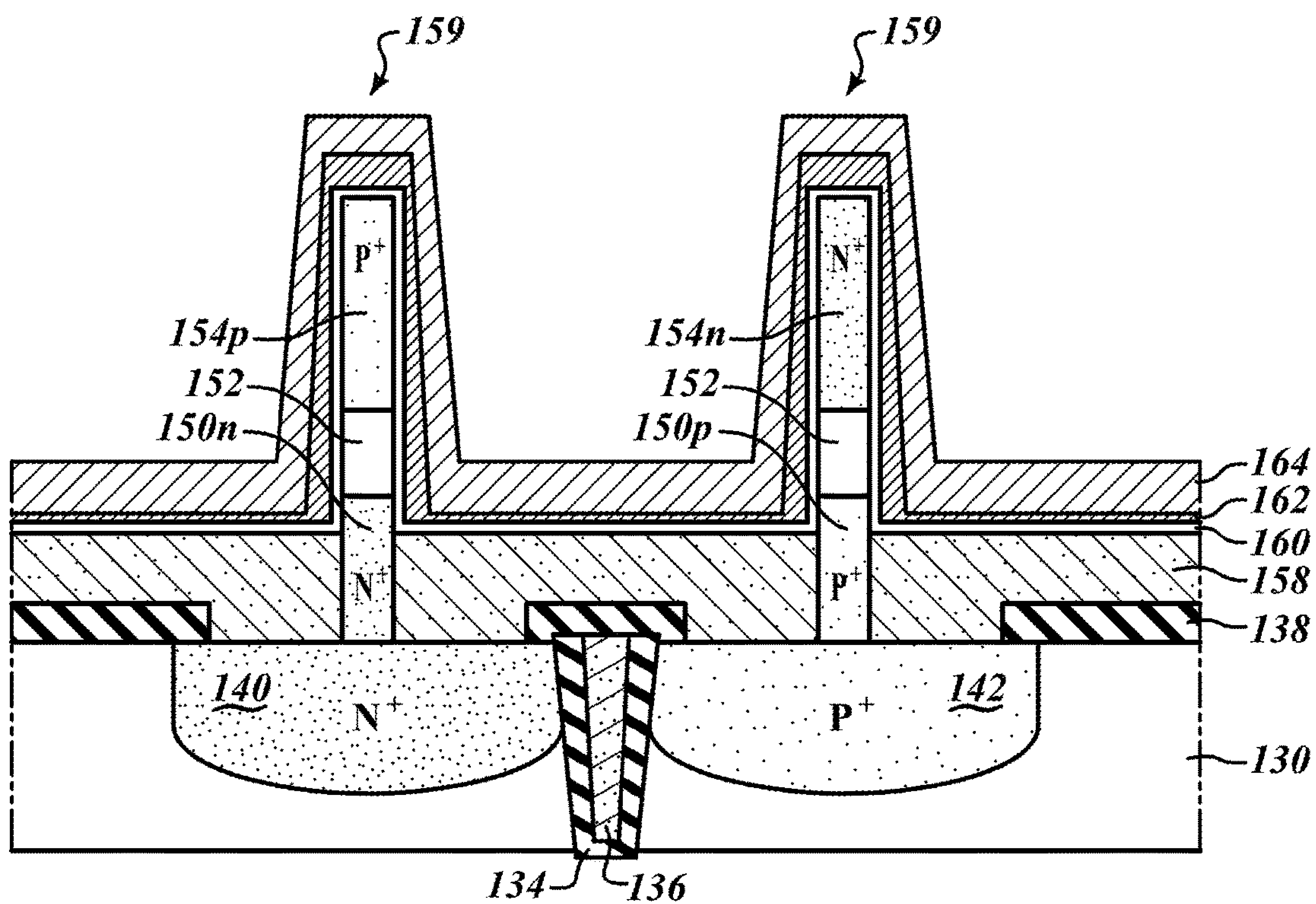

FIG. 6

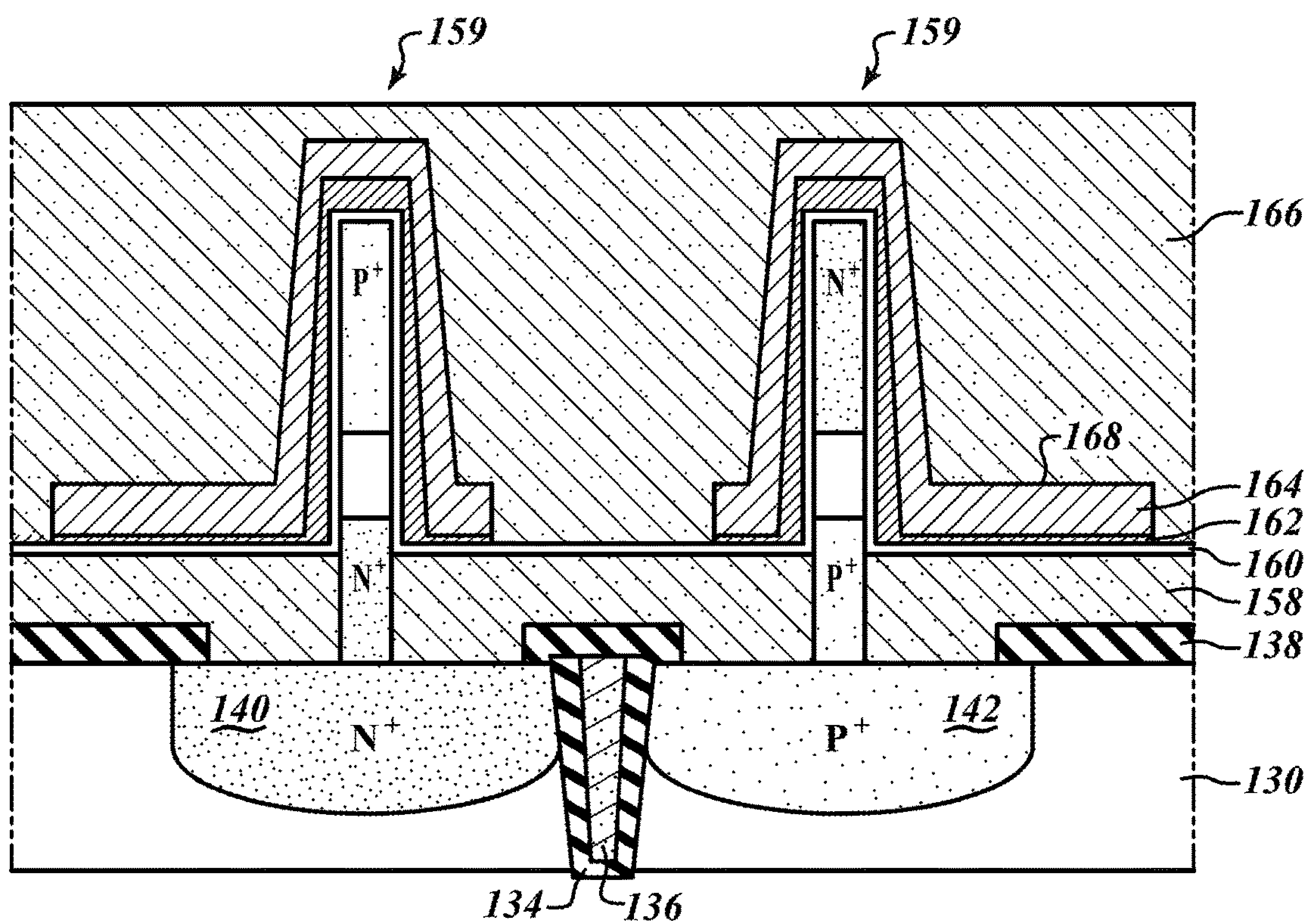

FIG. 7

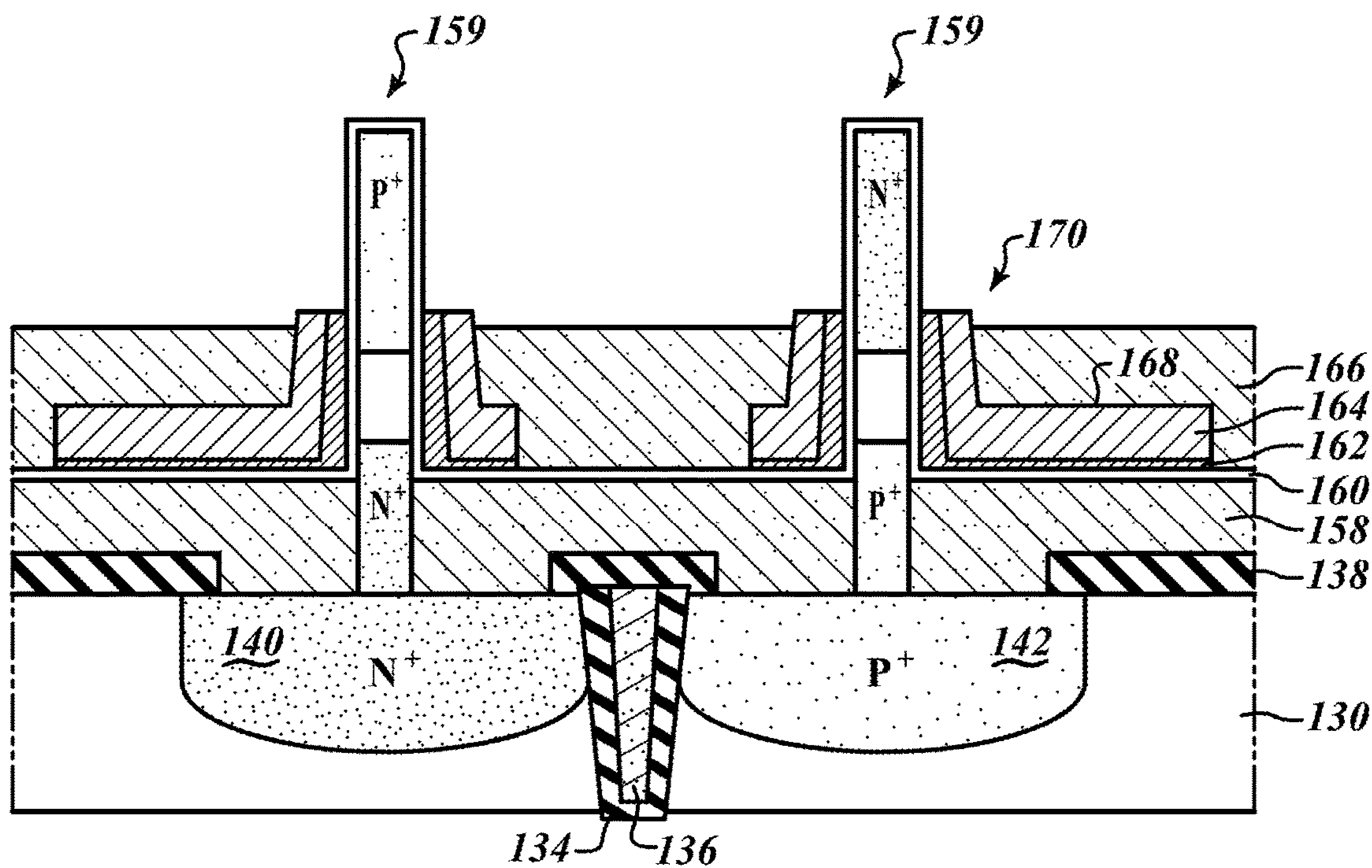

FIG.8

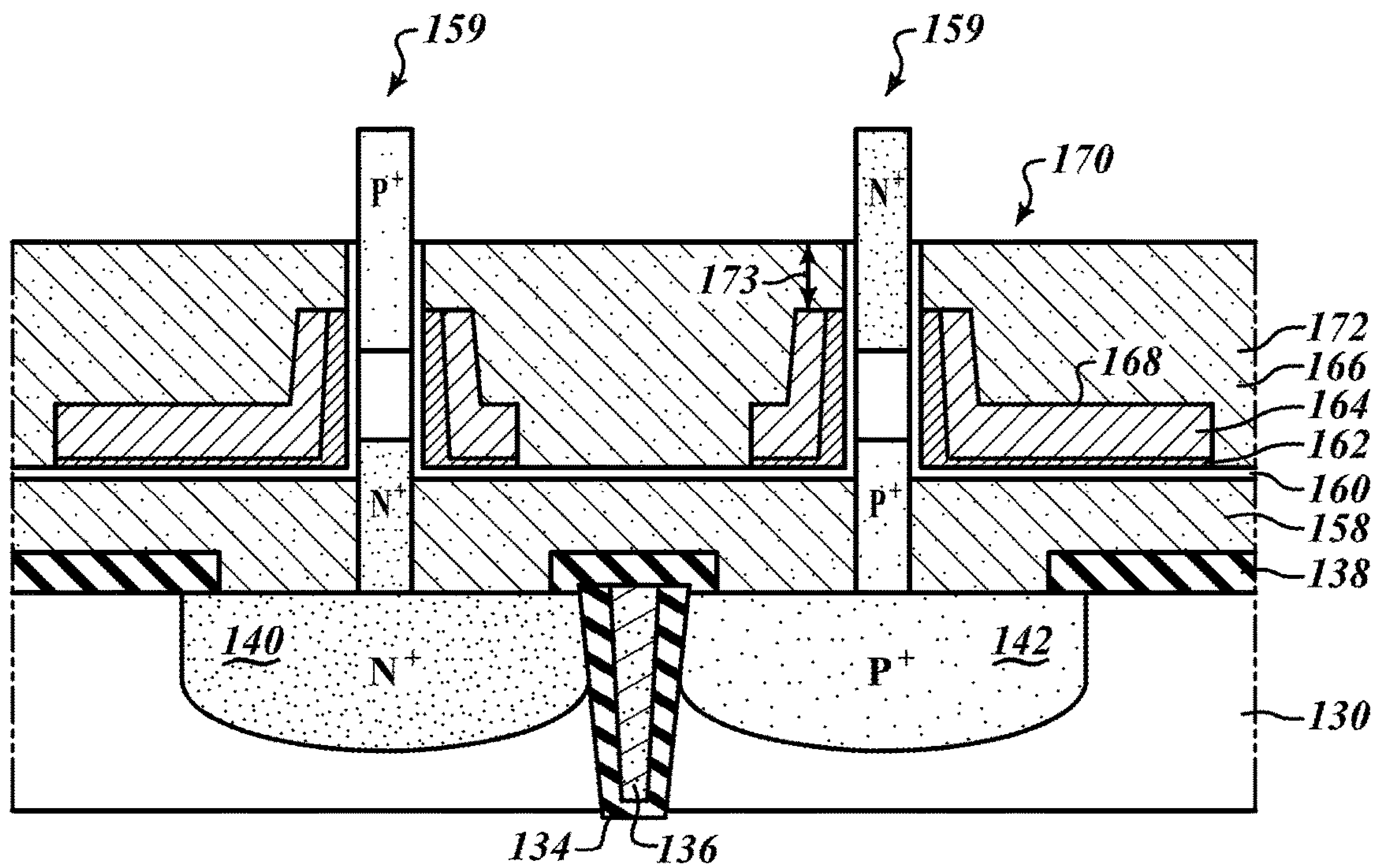

FIG.9

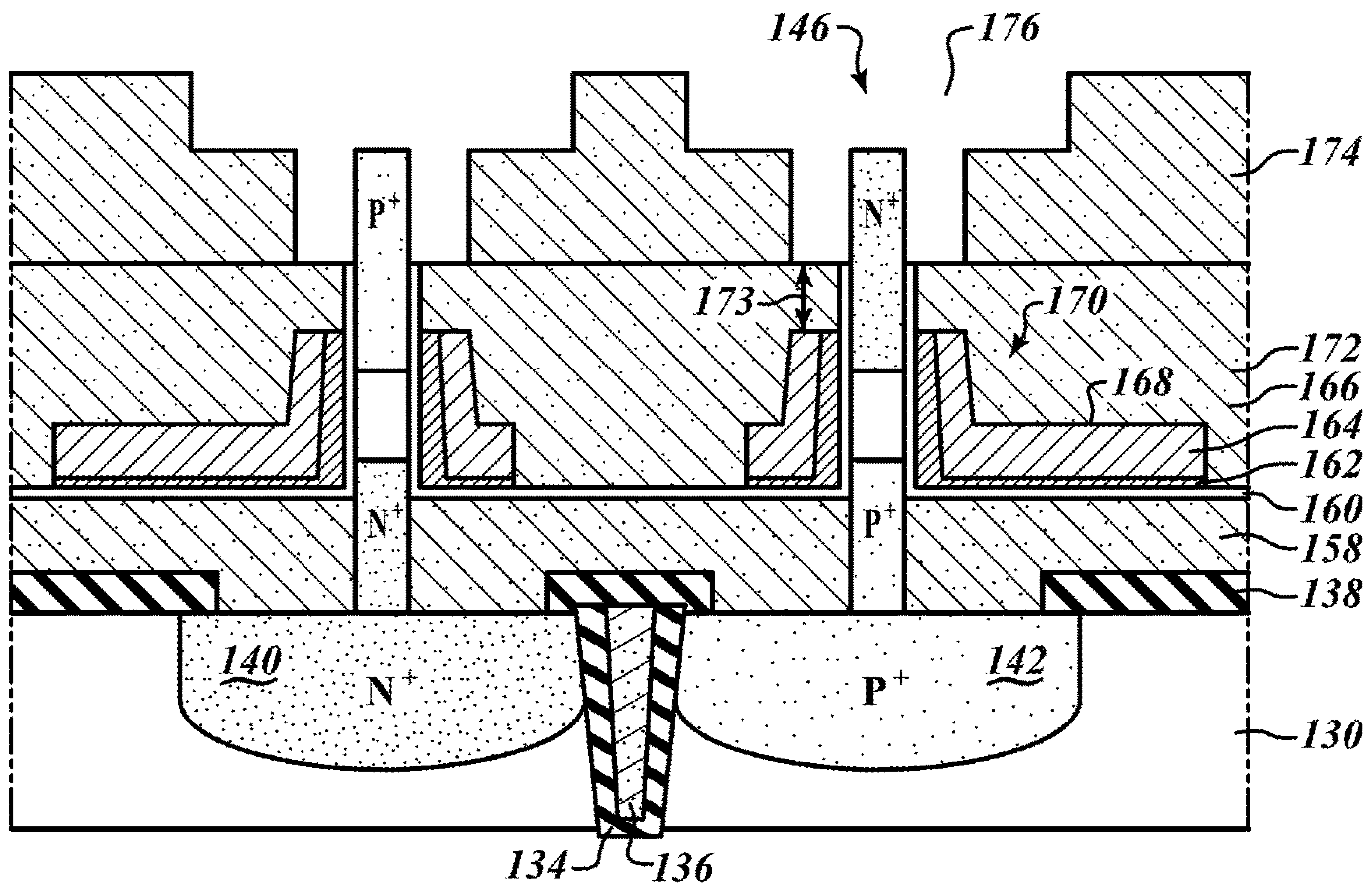

FIG. 10

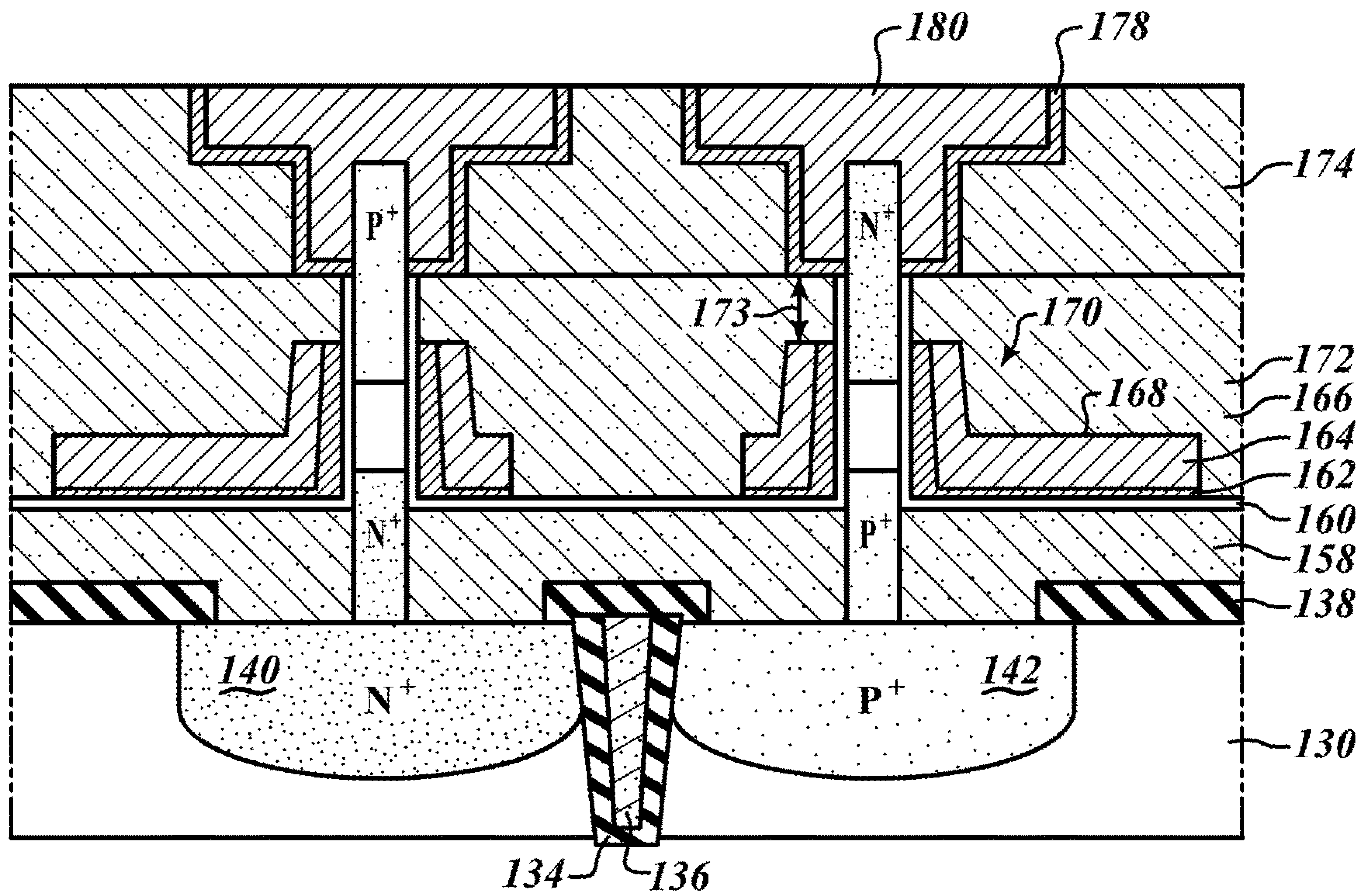

FIG. 11

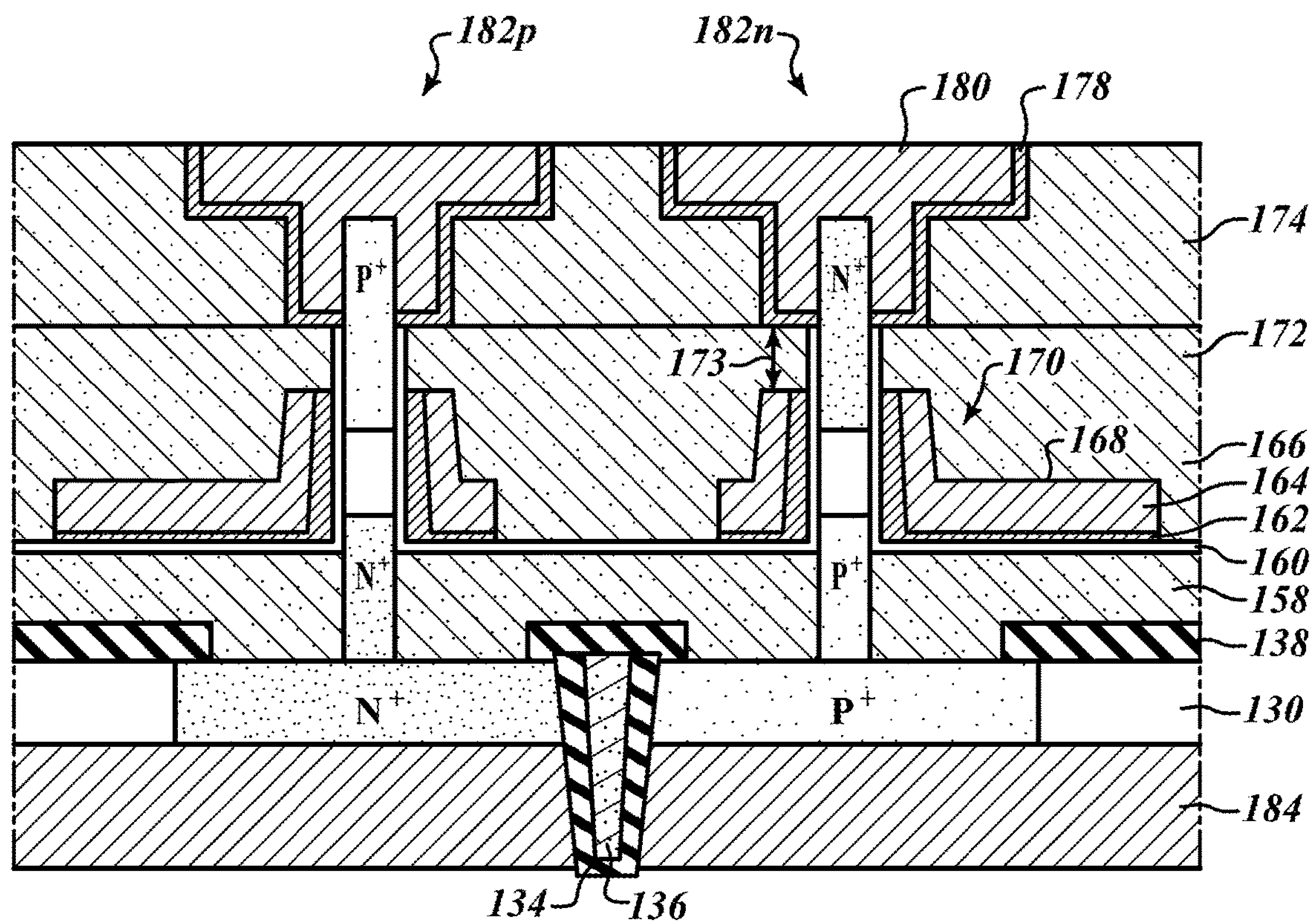

FIG.12

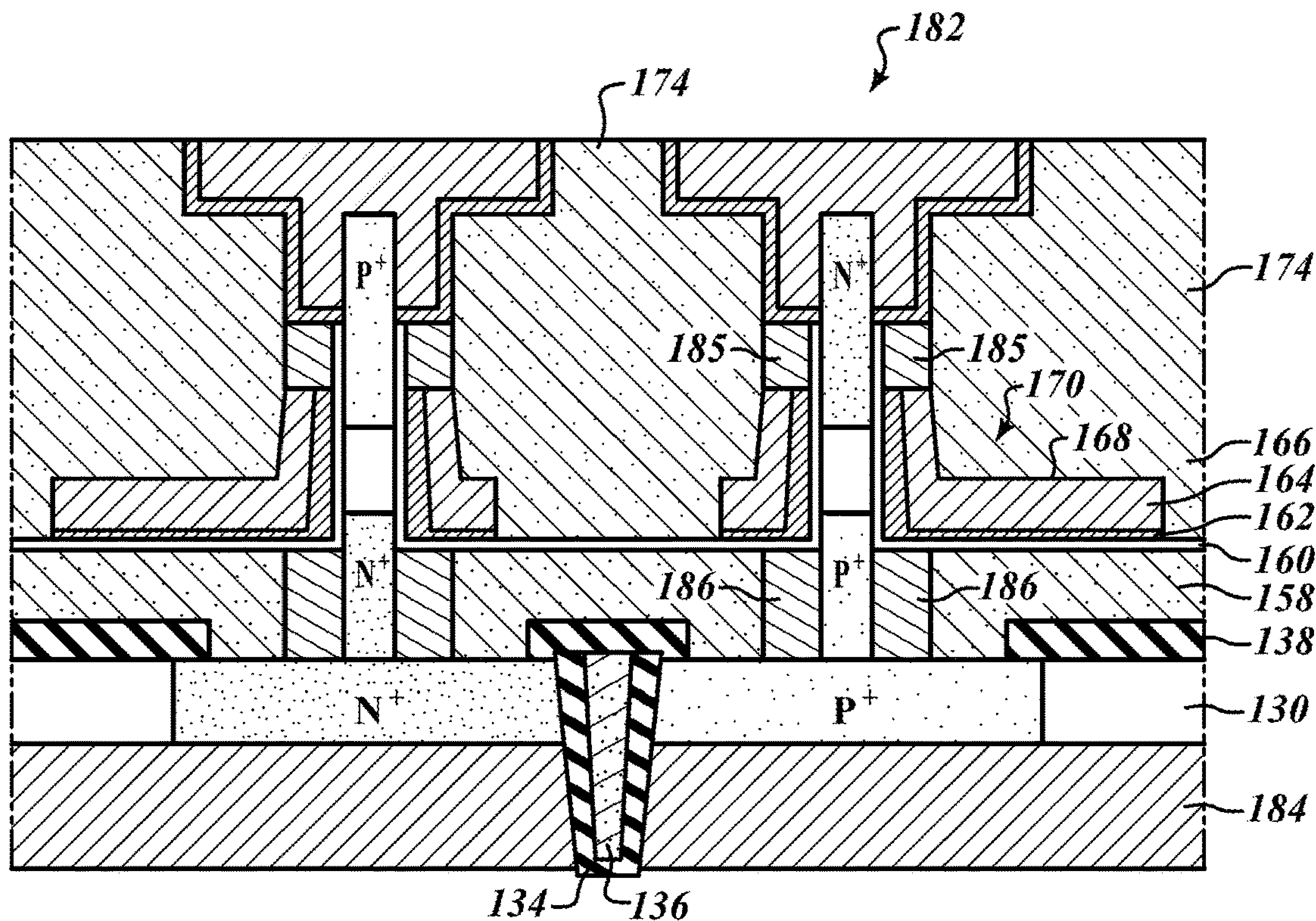

FIG.13

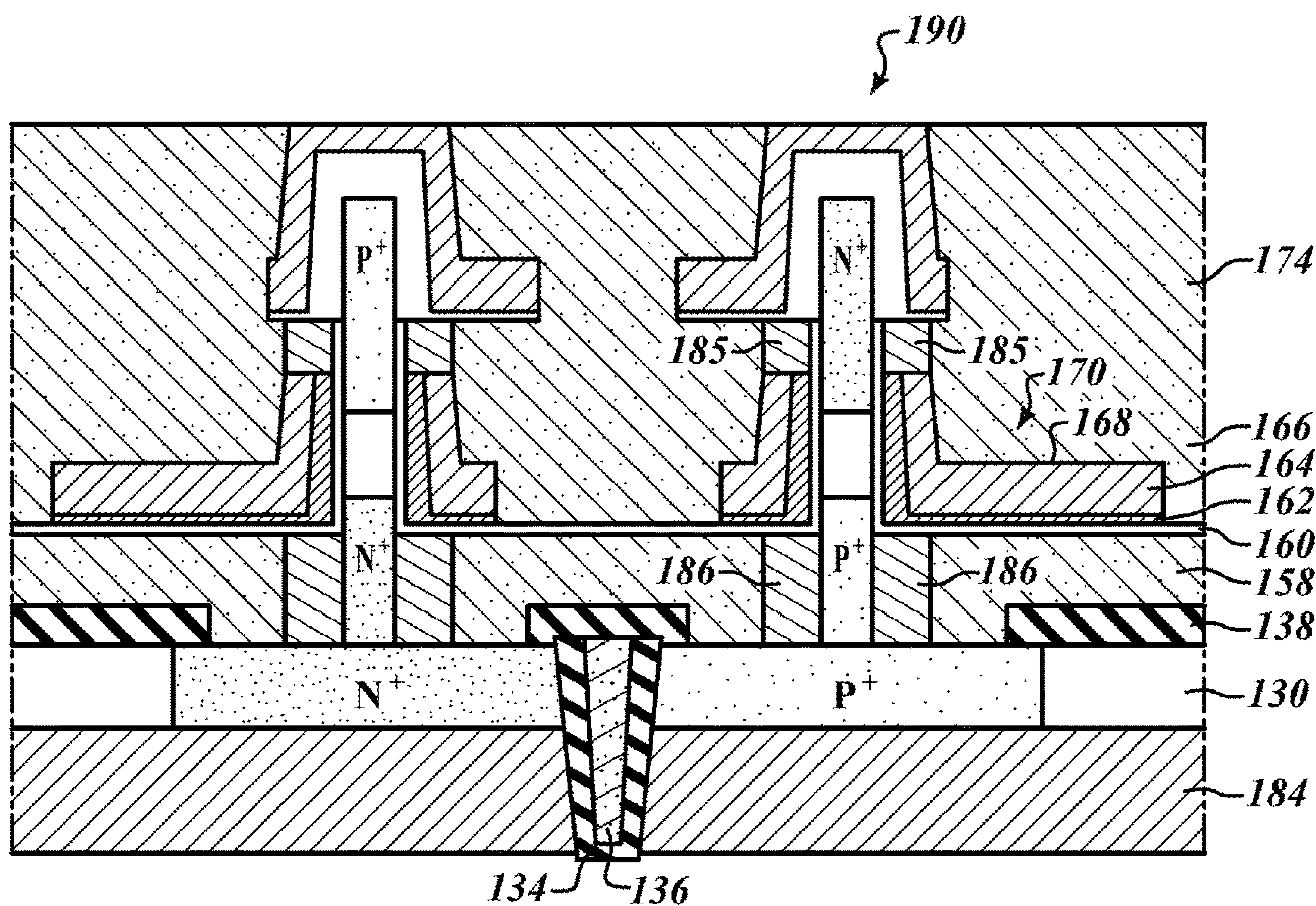

FIG.14

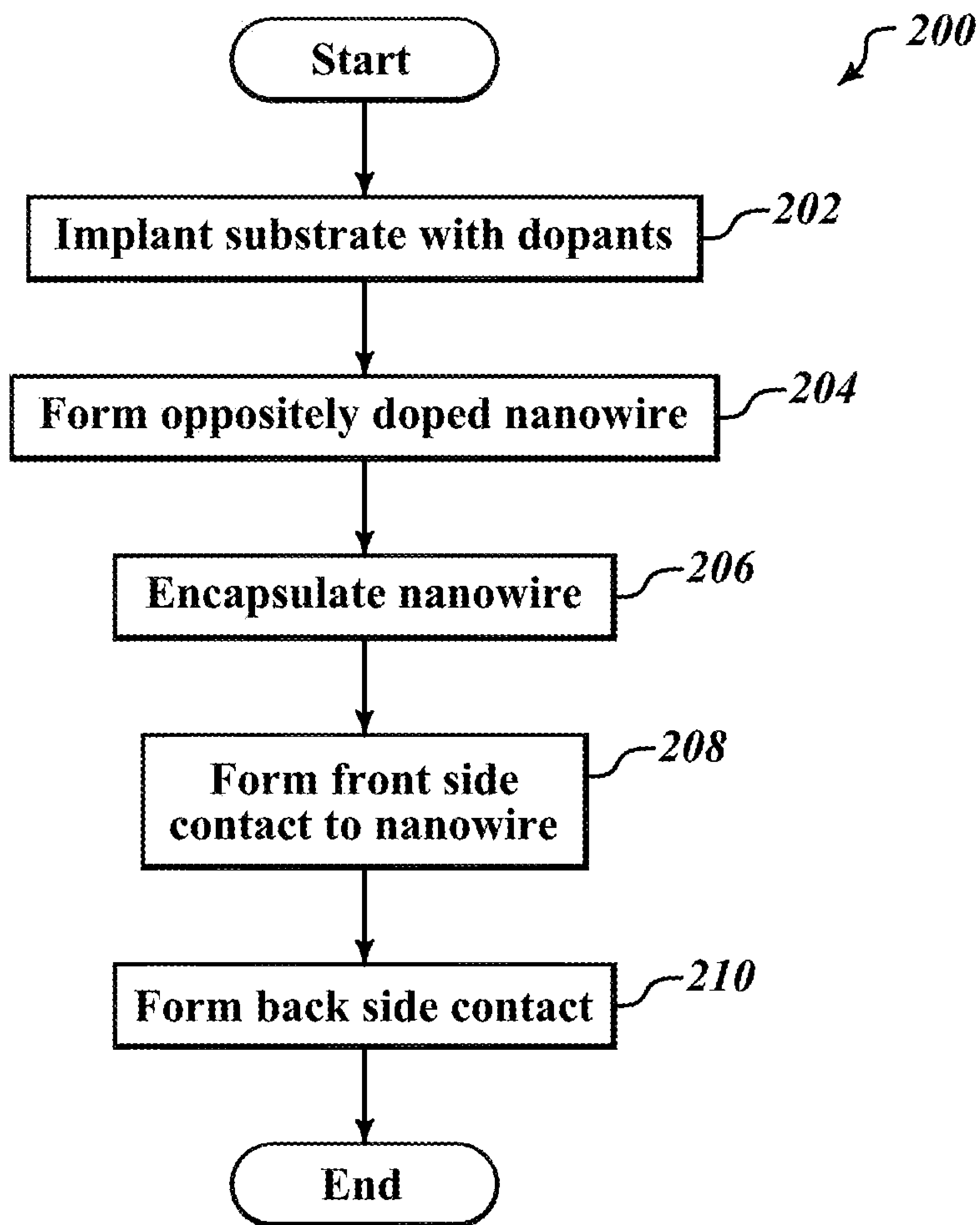

FIG.15

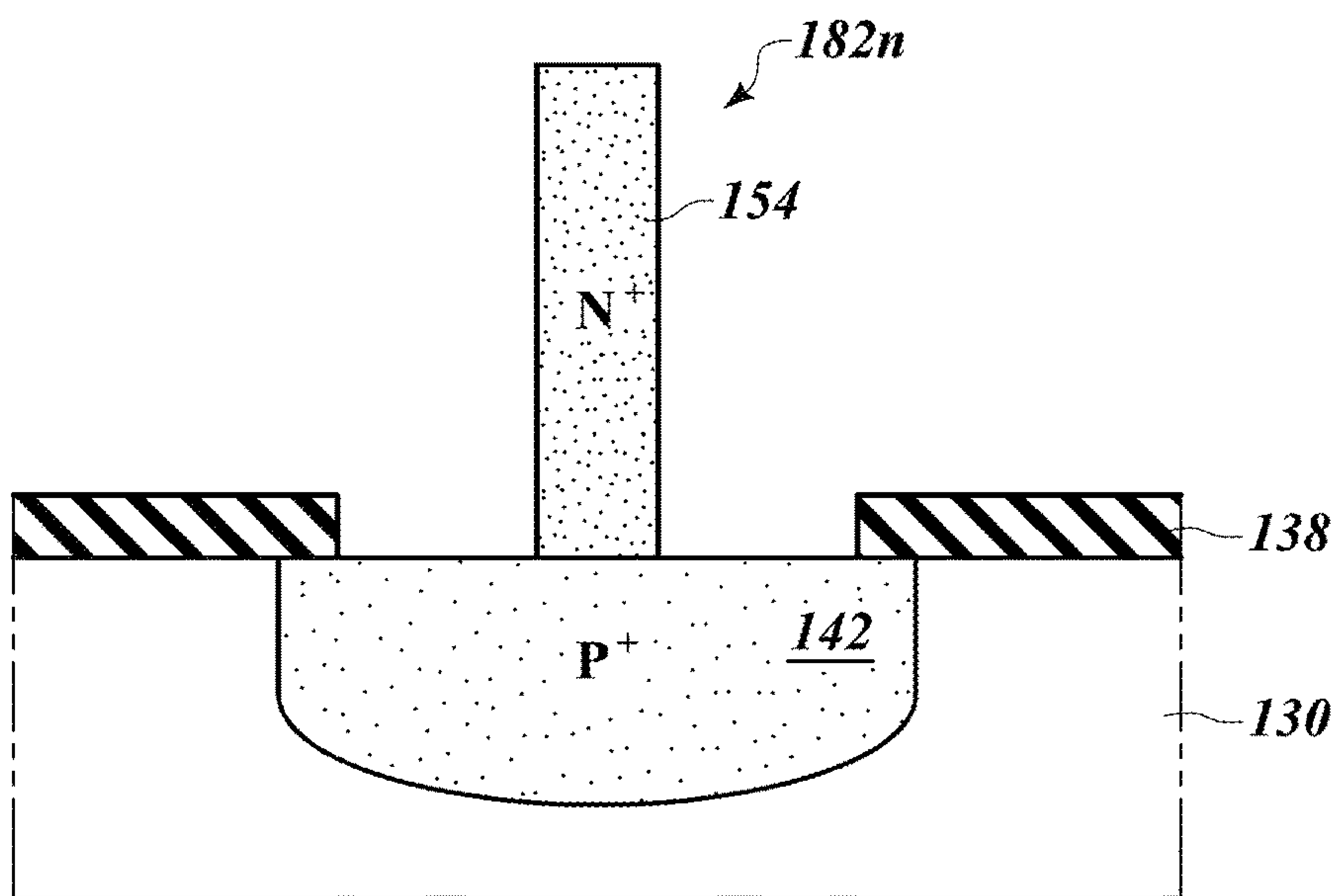

FIG.16

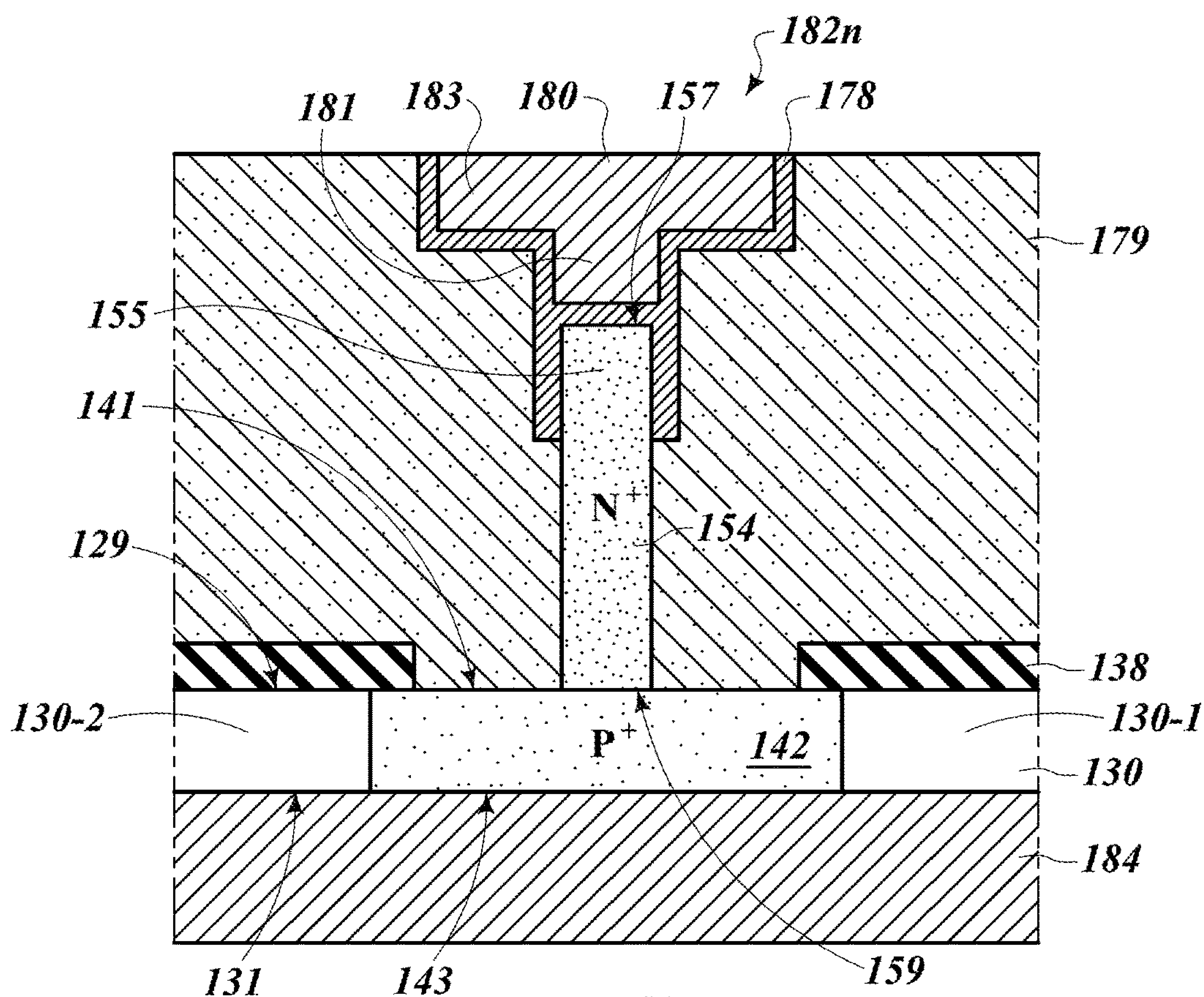

FIG.17

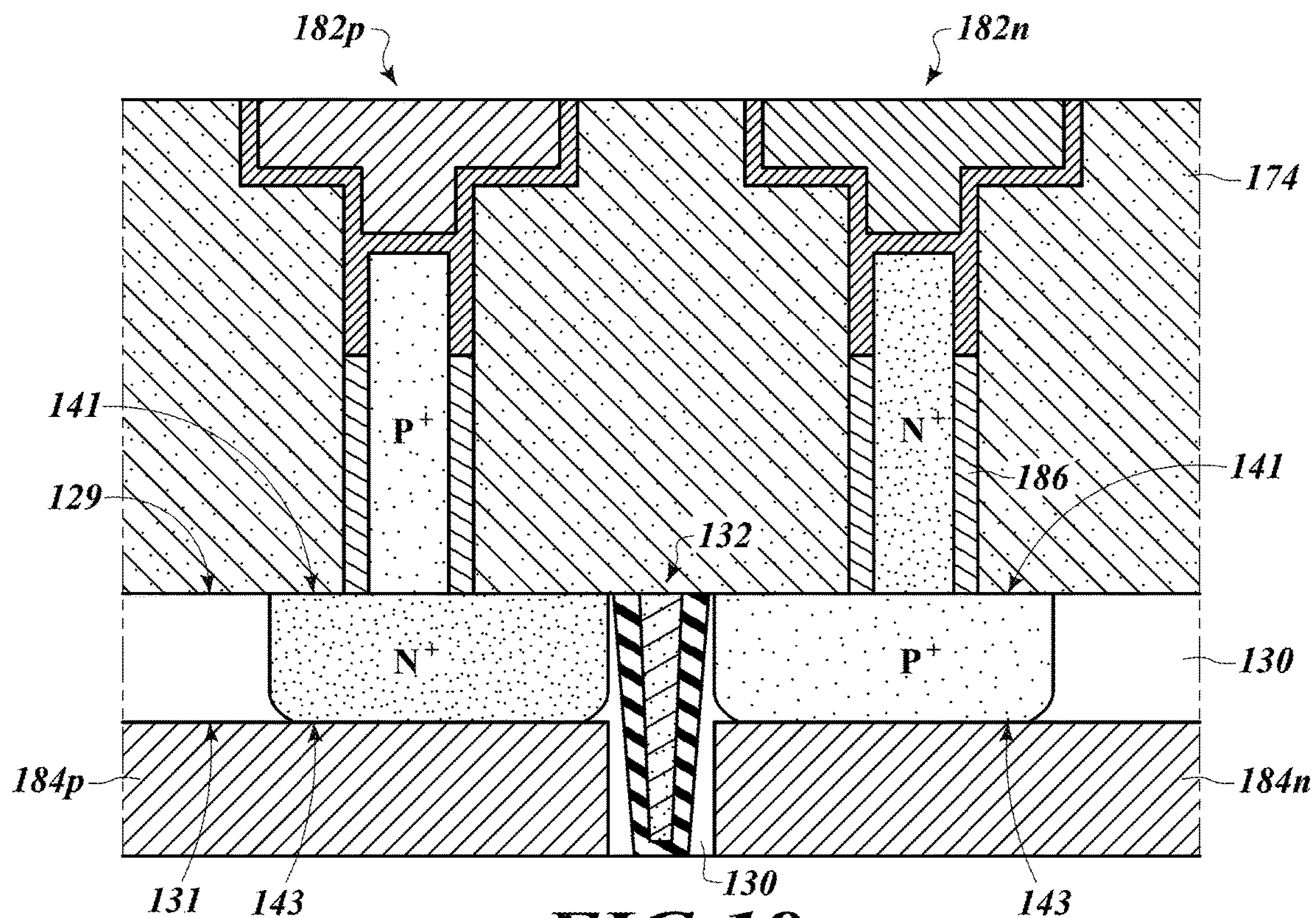

FIG. 18

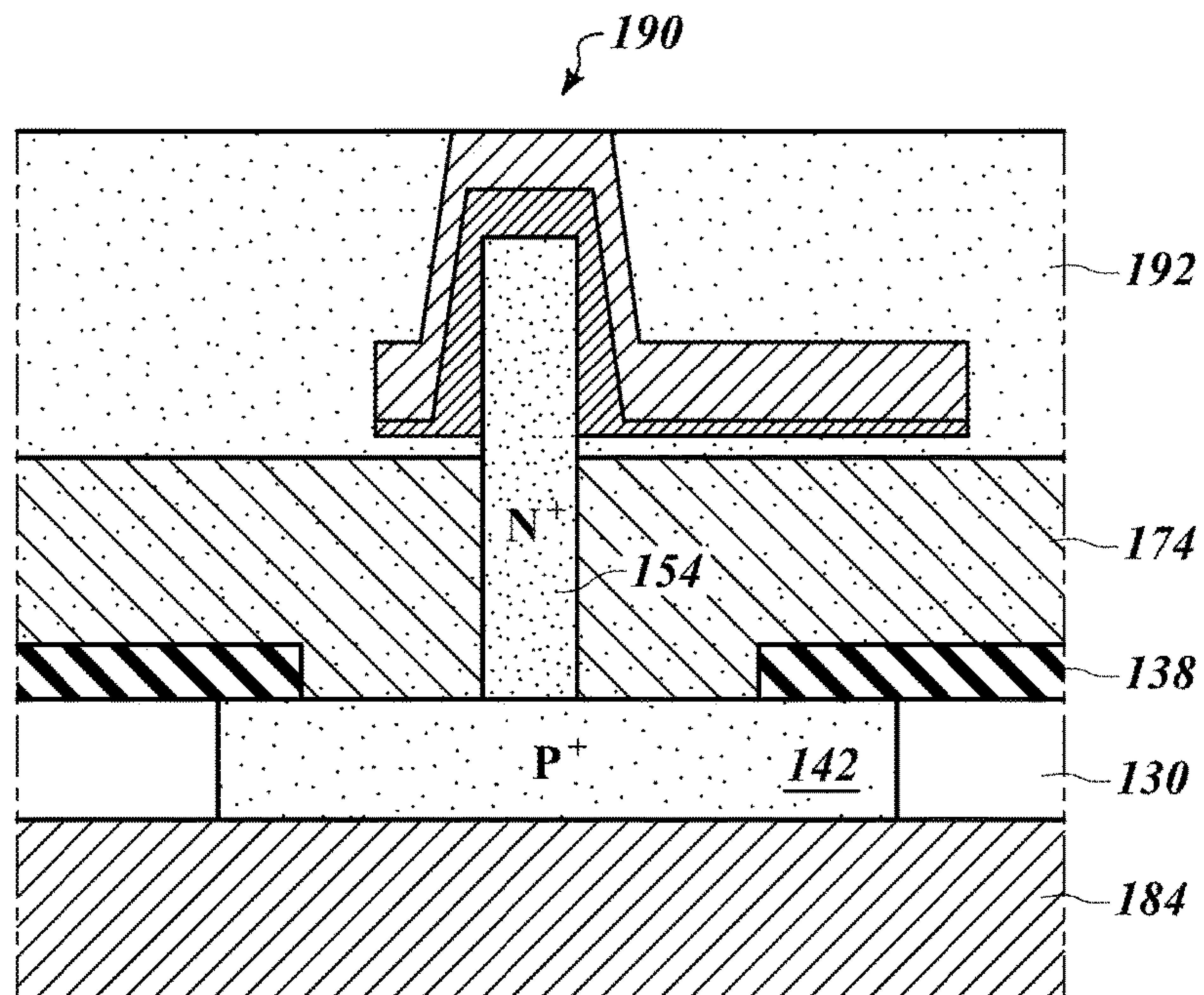

FIG. 19

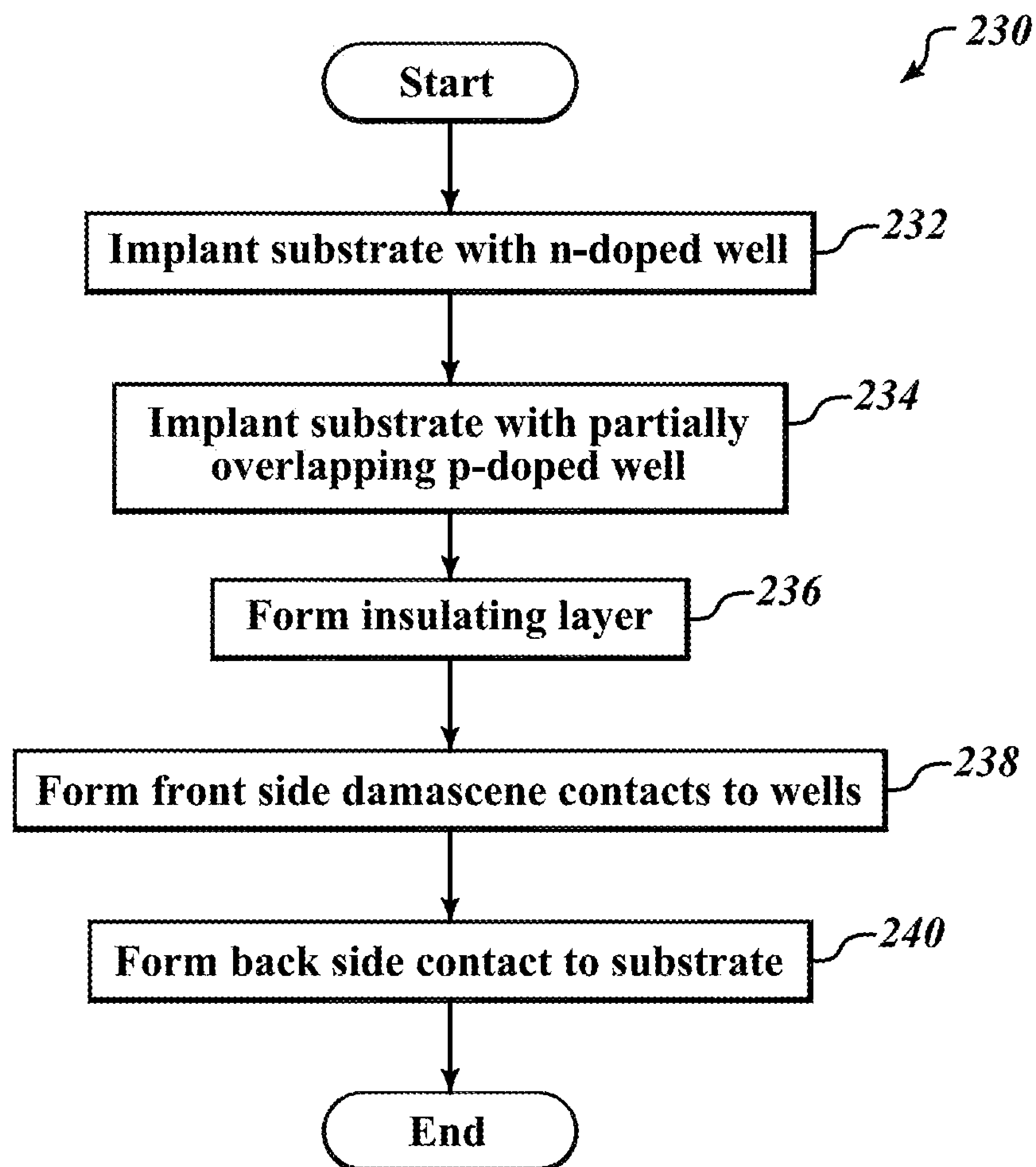

FIG.20

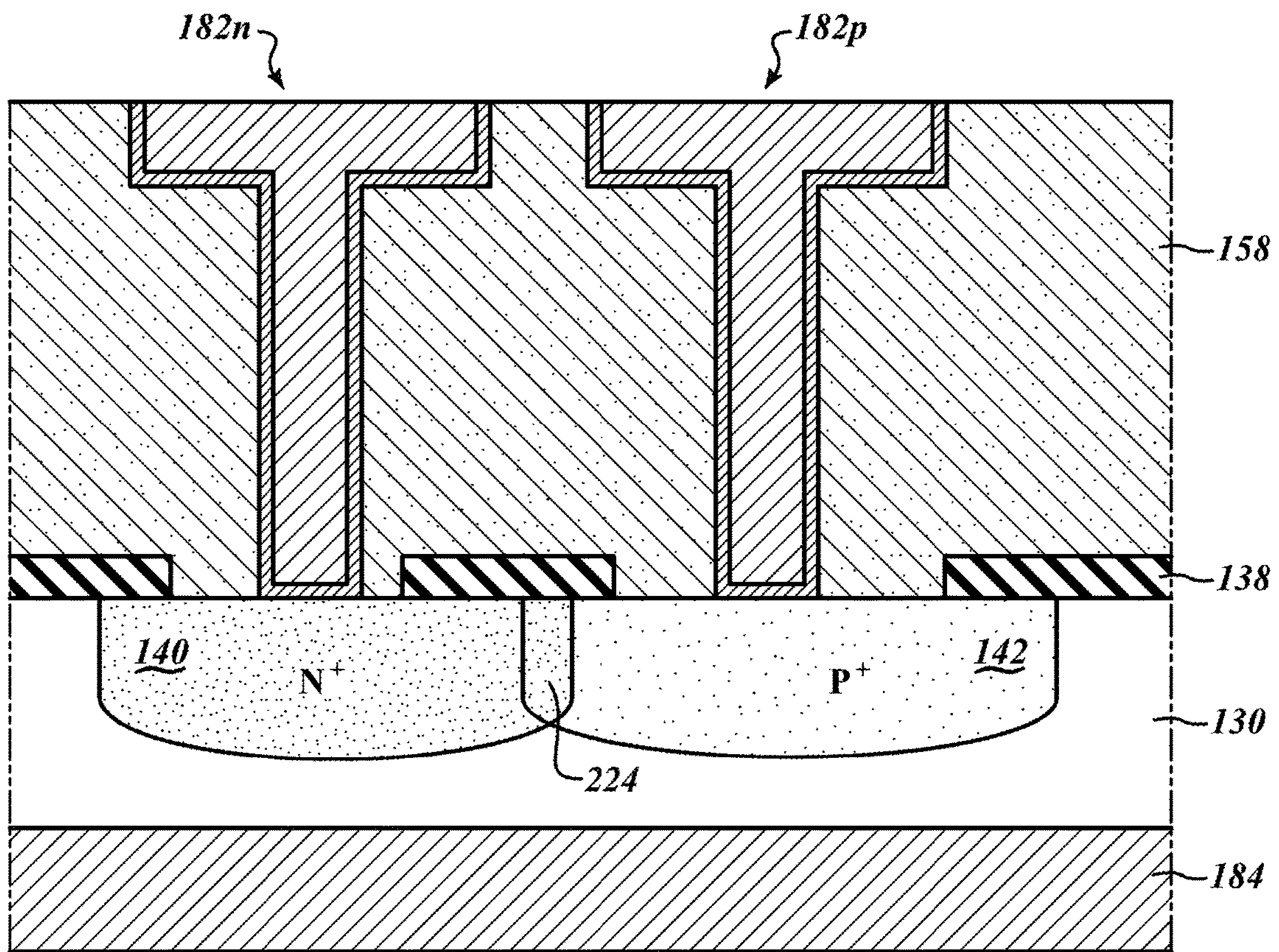

FIG.21

VERTICAL GATE-ALL-AROUND TFET

BACKGROUND

Technical Field

The present disclosure generally relates to various geometries for gate-all-around transistor devices built on a silicon substrate and, in particular, to transistors that are suitable for low-power applications.

Description of the Related Art

Conventional integrated circuits incorporate planar field effect transistors (FETs) in which current flows through a semiconducting channel between a source and a drain, in response to a voltage applied to a control gate. The semiconductor industry strives to obey Moore's law, which holds that each successive generation of integrated circuit devices shrinks to half its size and operates twice as fast. As device dimensions have shrunk below 100 nm, however, conventional silicon device geometries and materials have experienced difficulty maintaining switching speeds without incurring failures such as, for example, leaking current from the device into the semiconductor substrate. Several new technologies have emerged that allowed chip designers to continue shrinking gate lengths to 45 nm, 22 nm, and then as low as 14 nm. One particularly radical technology change entailed re-designing the structure of the FET from a planar device to a three-dimensional device in which the semiconducting channel was replaced by a fin that extends out from the plane of the substrate. In such a device, commonly referred to as a FinFET, the control gate wraps around three sides of the fin so as to influence current flow from three surfaces instead of one. The improved control achieved with a 3-D design results in faster switching performance and reduced current leakage. Building taller devices has also permitted increasing the device density within the same footprint that had previously been occupied by a planar FET. Examples of FinFET devices are described in further detail in U.S. Pat. No. 8,759,874 and U.S. Patent Publication 2014/0175554, assigned to the same assignee as the present patent application.

The FinFET concept was further extended by developing a gate-all-around FET, or GAA FET, in which the gate fully wraps around the channel for maximum control of the current flow therein. In the GAA FET, the channel can take the form of a cylindrical nanowire that is isolated from the substrate, in contrast to the peninsular fin. In the GAA FET the cylindrical nanowire is surrounded by the gate oxide, and then by the gate. Existing GAA FETs are oriented horizontally, such that the nanowire extends in a direction that is substantially parallel to the surface of the semiconductor substrate. GAA FETs are described in, for example, U.S. Patent Publication No. 2013/0341596 to Chang et al., of IBM, and in U.S. Patent Publication No. 2015/0372104 to Liu et al., assigned to the same assignee as the present patent application.

As integrated circuits shrink with each technology generation, more power is needed to drive a larger number of transistors housed in a smaller volume. To prevent chips from overheating, and to conserve battery power, each generation of transistors is designed to operate at a lower voltage and to dissipate less power. In a conventional complementary metal-oxide-semiconductor (CMOS) field effect transistor, the source and drain are doped to have a same polarity, e.g., both positive, in a P-FET, or both negative, in an N-FET. When the gate voltage applied to the transistor, V_G, exceeds a threshold voltage, V_T, the device turns on and current flows through the channel. When the gate voltage applied to the transistor is below the threshold voltage, the drain current, I_D, ideally is zero and the device is off. However, in reality, in the sub-threshold regime, there exists a small leakage current that is highly sensitive to the applied voltage. Over time, the leakage current drains charge from the power supply, e.g., a mobile phone battery or a computer battery, thus necessitating more frequent recharging. A change in gate voltage that is needed to reduce the sub-threshold leakage current by a factor of 10 is called the sub-threshold swing. It is desirable for the sub-threshold swing to be as small as possible. It is understood by those skilled in the art that MOSFETs have reached their lower limit of sub-threshold swing at 60 mV/decade. Thus, a different type of device is needed to further decrease the sub-threshold swing.

Tunneling field effect transistors (TFETs) are considered promising alternatives to conventional CMOS devices for use in future integrated circuits having low-voltage, low-power applications. Unlike a MOSFET, the source and drain of a TFET are doped to have opposite polarity. During operation of the TFET, charge carriers tunnel through a potential barrier rather than being energized to surmount the potential barrier, as occurs in a MOSFET. Because switching via tunneling requires less energy, TFETs are particularly useful in low-power applications such as mobile devices, for which battery lifetime is of utmost importance. Another reason TFETs provide enhanced switching performance for low-voltage operation is that TFETs have substantially smaller values of sub-threshold swing than MOSFETs.

BRIEF SUMMARY

A vertical TFET provides low-power, high-speed switching performance for transistors having critical dimensions below 7 nm. In one embodiment, the vertical TFET is implemented in silicon, using a gate-all-around (GAA) device architecture. The vertical GAA TFET is a linear, or 1-D, device in the form of a nanowire oriented transverse to planar front and back surfaces of the silicon substrate. The nanowire includes a lower drain region, a channel, and an upper source region, which are grown epitaxially from the doped well. The channel region is made of intrinsic silicon, while the source and drain regions are doped in-situ. An annular gate surrounds the channel region, capacitively controlling current flow through the channel from all sides. The source is electrically accessible via a front side contact, while the drain is accessed via a backside contact that provides low contact resistance and also serves as a heat sink.

Reliability of vertical TFET integrated circuits is enhanced by coupling the TFETs to electrostatic discharge (ESD) diodes. Both vertical and horizontal ESD diode configurations are described herein. ESD diodes provide protection for TFETs and other GAA transistors against high currents and voltages, especially in analog and I/O applications.

Fabrication of the vertical TFETs and ESD diodes as described herein is compatible with conventional CMOS manufacturing processes. Low-power operation allows the vertical TFET to provide a high current density, or "current per footprint" on a chip, compared with conventional planar

transistors. The high current density allowed by these devices makes them good candidates for memory applications, e.g., for SRAM arrays.

BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWINGS

In the drawings, identical reference numbers identify similar elements or acts. The sizes and relative positions of elements in the drawings are not necessarily drawn to scale.

FIG. **1** is a flow diagram showing steps in a method of fabricating a pair of n-type and p-type vertical GAA TFETs as illustrated in FIGS. **2-12**, according to one embodiment described herein.

FIGS. **2-12** are cross-sectional views of the vertical GAA TFETs at successive steps during fabrication using the method shown in FIG. **1**.

FIGS. **13-14** are cross-sectional views of alternative embodiments of completed n-type and p-type vertical GAA TFETs shown in FIG. **12**, wherein each embodiment has a different contact configuration, as described herein.

FIG. **15** is a flow diagram showing steps in a method of fabricating a pair of vertical diodes as illustrated in FIGS. **16-18**, according to a first embodiment as described herein.

FIGS. **16-18** are cross-sectional views of the pair of vertical diodes at successive steps during fabrication using the method shown in FIG. **15**.

FIG. **19** is a cross-sectional view of a completed vertical diode, according to a second embodiment as described herein.

FIG. **20** is a flow diagram showing steps in an alternative method of fabricating vertical diodes and a horizontal diode, according to one embodiment described herein.

FIG. **21** is a cross-sectional view of a completed pair of vertical diodes and a horizontal diode fabricated using the method shown in FIG. **20**.

DETAILED DESCRIPTION

In the following description, certain specific details are set forth in order to provide a thorough understanding of various aspects of the disclosed subject matter. However, the disclosed subject matter may be practiced without these specific details. In some instances, well-known structures and methods of semiconductor processing comprising embodiments of the subject matter disclosed herein have not been described in detail to avoid obscuring the descriptions of other aspects of the present disclosure.

Unless the context requires otherwise, throughout the specification and claims that follow, the word "comprise" and variations thereof, such as "comprises" and "comprising" are to be construed in an open, inclusive sense, that is, as "including, but not limited to."

Reference throughout the specification to "one embodiment" or "an embodiment" means that a particular feature, structure, or characteristic described in connection with the embodiment is included in at least one embodiment. Thus, the appearance of the phrases "in one embodiment" or "in an embodiment" in various places throughout the specification are not necessarily all referring to the same aspect. Furthermore, the particular features, structures, or characteristics may be combined in any suitable manner in one or more aspects of the present disclosure.

Reference throughout the specification to integrated circuits is generally intended to include integrated circuit components built on semiconducting substrates, whether or not the components are coupled together into a circuit or able to be interconnected. Throughout the specification, the term "layer" is used in its broadest sense to include a thin film, a cap, or the like and one layer may be composed of multiple sub-layers. Throughout the specification, the terms "N-well" and "N-well region" are used synonymously in reference to negatively-doped regions of a semiconductor. Likewise, the terms "P-well" and "P-well region" are also used synonymously in reference to positively-doped regions of a semiconductor.

Reference throughout the specification to conventional thin film deposition techniques for depositing silicon nitride, silicon dioxide, metals, or similar materials include such processes as chemical vapor deposition (CVD), low-pressure chemical vapor deposition (LPCVD), metal organic chemical vapor deposition (MOCVD), plasma-enhanced chemical vapor deposition (PECVD), plasma vapor deposition (PVD), atomic layer deposition (ALD), molecular beam epitaxy (MBE), electroplating, electro-less plating, and the like. Specific embodiments are described herein with reference to examples of such processes. However, the present disclosure and the reference to certain deposition techniques should not be limited to those described. For example, in some circumstances, a description that references CVD may alternatively be done using PVD, or a description that specifies electroplating may alternatively be accomplished using electro-less plating. Furthermore, reference to conventional techniques of thin film formation may include growing a film in-situ. For example, in some embodiments, controlled growth of an oxide to a desired thickness can be achieved by exposing a silicon surface to oxygen gas or to moisture in a heated chamber.

Reference throughout the specification to conventional photolithography techniques, known in the art of semiconductor fabrication for patterning various thin films, includes a spin-expose-develop process sequence typically followed by an etch process. Alternatively or additionally, photoresist can also be used to pattern a hard mask (e.g., a silicon nitride hard mask), which, in turn, can be used to pattern an underlying film.

Reference throughout the specification to conventional etching techniques known in the art of semiconductor fabrication for selective removal of polysilicon, silicon nitride, silicon dioxide, metals, photoresist, polyimide, or similar materials includes such processes as wet chemical etching, reactive ion (plasma) etching (RIE), washing, wet cleaning, pre-cleaning, spray cleaning, chemical-mechanical planarization (CMP) and the like. Specific embodiments are described herein with reference to examples of such processes. However, the present disclosure and the reference to certain deposition techniques should not be limited to those described. In some instances, two such techniques may be interchangeable. For example, stripping photoresist may entail immersing a sample in a wet chemical bath or, alternatively, spraying wet chemicals directly onto the sample.

Specific embodiments are described herein with reference to vertical gate-all-around TFET devices that have been produced; however, the present disclosure and the reference to certain materials, dimensions, and the details and ordering of processing steps are exemplary and should not be limited to those shown.

Turning now to the figures, FIG. **1** shows steps in a method **100** of fabricating a pair of vertical GAA TFETs **182***n,p*, according to one embodiment. The completed GAA TFET devices produced by the method **100** are shown in FIG. **12**. Alternative embodiments of the GAA TFET, formed by modifying the method **100**, are shown in FIGS.

13-14. Each vertical GAA TFET is in the form of an epitaxially grown pillar having a doped lower drain region, a central channel region made of intrinsic silicon, and an upper source region doped to have a polarity opposite that of the lower drain region. The central channel region extends between the source and drain regions. A gate structure surrounds the channel region so as to influence current flow between the source and drain regions in response to an applied voltage. Steps in the method 100 are further illustrated by FIGS. 2-12, and described below.

At 102, an isolation region 132 is formed in a silicon substrate 130 to separate p-type and n-type devices that will subsequently be formed. The isolation region 132 includes a liner 134 made of, for example, silicon nitride, and a silicon dioxide core 136, as shown in FIG. 2.

At 104, with reference to FIG. 3, a silicon substrate 130 having a <111> crystal orientation is doped to form an N-well 140 and a P-well 142 by ion implantation using a hard mask 138, as is well known in the art. The exemplary hard mask 138 is made of silicon dioxide (SiO_2) having a thickness in the range of about 10 nm-50 nm. The hard mask 138 is grown or deposited over the surface of the silicon substrate 130, and is patterned with a first opening 139 to define the P-well 142, for example. Positive dopants such as boron ions are implanted into the silicon substrate 130 through the first opening 139 and then annealed to drive in the dopants to a selected depth 144. In one embodiment, the boron concentration is desirably within the range of about 1.0 E16 cm^{-3}-5.0 E20 cm^{-3}, targeted at 5.0 E19 cm^{-3}. Then the hard mask 138 is stripped, re-formed, and patterned with a second opening 146 for the N-well 140. Negative dopants such as phosphorous ions or arsenic ions are then implanted into the silicon substrate 130 through the second opening 146, followed by annealing to drive in the negative dopants to the selected depth 144. In one embodiment, the n-dopant concentration is desirably within the range of about 1.0 E16 cm^{-3}-3.0 E20 cm^{-3}, targeted at 2.0 E19 cm^{-3}. The first and second openings 139 and 146, respectively, can be the same size or different sizes, within a wide range of about 2 nm-200 nm.

At 106, epitaxial drain regions 150*n* and 150*p* are formed by epitaxial growth from the N-well and P-well regions 140 and 142 as shown in FIG. 4, extending in a transverse orientation to the silicon substrate 130. The hard mask 138 is stripped, re-formed, and re-patterned with a smaller opening 148*n*, for example. The drain region 150*n* is then grown epitaxially from a top surface of the N-well 140. The hard mask 138 is again stripped, re-formed, and re-patterned with a small opening 148*p*. The drain region 150*p* is then grown epitaxially from a top surface of the P-well 142. The drain regions 150*n* and 150*p* are grown to a height anywhere within the wide range of about 5 nm-500 nm, with doping occurring in-situ during the epitaxial growth. The order in which the n- and p-type structures are patterned and grown is exemplary as described above, and can be reversed.

At 108, nanowires 151*n* and 151*p* containing intrinsic silicon channels 152 and source regions 154*n* and 154*p*, respectively, are grown epitaxially from the drain regions 150*n* and 150*p* to complete formation of the pillars. First, cylindrical channels 152 made of intrinsic silicon are grown to a height within the range of 2 nm-100 nm. Then, a source region 154*n* made of indium arsenide (InAs), an n-type material, is selectively grown from the intrinsic silicon channel 152 that overlies the P-well 142 while a source region 154*p* made of a boron-SiGe compound ($BSi_xGe_{(1-x)}$), a p-type material, is selectively grown from the intrinsic silicon channel 152 that overlies the N-well 140, as shown in FIG. 4. The source regions 154*n* and 154*p* are each grown to a thickness within the range of about 5 nm-500 nm. The epitaxial nanowires 151*n* and 151*p*, as grown, have widths 148*p* and 148*n*, respectively. Next, the epitaxial nanowires 151*n* and 151*p* are trimmed to a target critical dimension (CD) 156, as needed, as shown in FIG. 5 using a plasma etching process. The CD 156 can be defined using a silicon nitride hard mask, for example. In one embodiment, epitaxial growth of the regions 150*n*, 150*p*, 152, 154*p*, and 154*n* may occur inside patterned pillar-shaped holes formed in an insulating material, to provide support for the vertical nanowires 151*n* and 151*p*. The insulating material can include one or more layers, and the pillar-shaped holes may further include liners. The pillar-shaped holes may be used to define CD boundaries for the vertical nanowires 151*n* and 151*p*.

At 110, the epitaxial nanowires 151*n* and 151*p* are encapsulated by spin-coating a thick layer of benzocyclobutene (BCB) 158 to cover the epitaxial nanowires, and then performing a chemical-mechanical planarization (CMP) operation that stops on the InAs and $BSi_xGe_{(1-x)}$ source regions 154*n* and 154*p*, respectively.

At 112, the BCB encapsulant 158 is etched back to reveal the epitaxial nanowires 151*n* and 151*p* and top portions of the drain regions 150*n* and 150*p*, so that multi-layer gate structures 159 can be formed in contact with the exposed nanowires, as shown in FIG. 6, according to one embodiment. The multi-layer gate structures 159 include a dielectric sheath wrapped around the channel and a metal gate wrapped around the dielectric sheath. The etch-back process can be, for example, a plasma etch process that uses an O_2—SF_6 chemistry. Once the epitaxial nanowires are exposed, a gate oxide 160 is conformally deposited. The gate oxide 160 is desirably a high dielectric constant, or high-k, material of thickness 1 nm-10 nm, such as HfO_2 or Al_2O_3, for example. Next, a work function material 162 of thickness 1 nm-20 nm is conformally deposited, followed by a gate metal 164 of thickness 10 nm-200 nm. The gate metal 164 and the work function material 162 can be, for example, copper (Cu), aluminum (Al), tungsten (W), platinum (Pt), gold (Au), titanium nitride (TiN), tantalum nitride (TaN), titanium carbon (TiC), titanium-tungsten (TiW_x), or combinations thereof. Regions of the gate stack located between adjacent nanowires are then etched away as shown in FIG. 7, while regions of the gate stack outside the epitaxial nanowires remain to form gate contact landing pads 168.

At 114, the gate structures 159 are encapsulated. In one embodiment, encapsulation is accomplished by spin coating a second BCB layer 166, followed by a CMP process that is targeted to stop when a selected BCB thickness has been reached, above the metal gate structures 159. Alternatively, the planarization process can stop on the metal gate structures 159.

At 116, the second BCB layer 166 is etched back to reveal portions of the metal gate structures 159 covering the source regions 154*n*, 154*p* to a level in the range of about 1 nm-300 nm above the intrinsic silicon channel 152 to expose the gate metal 164. Then, the gate metal 164 and the work function material 162 are etched away to reveal the gate oxide 160 covering the source regions, thus leaving behind completed gates 170 surrounding the intrinsic silicon channel regions.

At 118, epitaxial nanowires 151*p,n* are encapsulated. In one embodiment, encapsulation is accomplished by spin coating a third BCB layer 172, followed by a CMP process that is targeted to stop when a selected BCB thickness has been reached, above the gate structures 159.

At **120**, the third BCB layer **172** and the gate oxide **160** are etched back to a height **173** above a top surface of the gate metal **164**, to reveal the top 3 nm-300 nm of the InAs and $BSi_xGe_{(1-x)}$ source regions **154***n,p*, as shown in FIGS. **9-12**.

At **122**, source regions **154***n,p* are encapsulated. In one embodiment, encapsulation is accomplished by spin coating a fourth BCB layer **174**, followed by a CMP process that is targeted to stop when a selected BCB thickness has been reached, above the gate structures **159**. Alternatively, an oxide deposited using a high density plasma (HDP) process can be used in place of the fourth BCB layer **174**.

At **124**, contacts are made to the source regions. In one embodiment, a dual damascene process is used to form front side source contacts **182** to the epitaxial nanowire and a metal interconnect layer, while backside contacts **184** are made to the epitaxial drain regions **150***n,p* via the implant-doped well regions. First, dual damascene trenches **176** are etched in the fourth BCB layer **174**, as well as contact holes surrounding the source regions **154***n,p*, as shown in FIG. **10**. Then the source regions **154***n,p* can be reacted with metal to form a silicide e.g., TiSi, NiSiPt, or a dual silicide such as Pt, Ir for the p-type source **154***p*, or Er, Yb for the n-type source **154***n* prior to filling the trenches and contact holes using established methods familiar to those skilled in the art of damascene processing. The metal fill desirably includes a liner made of, for example, TiN or TiC. The metal is then planarized to stop on the fourth BCB layer, as shown in FIG. **11**. Finally, metal contacts of thickness 5 nm-50 μm are made to the backside of the wafer to contact the N-well **140** and the P-well **142**, as shown in FIG. **12**.

FIG. **13** shows a second embodiment of the vertical GAA TFET in which additional spacers are wrapped around the pillars between the gate structures **170** and the source and drain regions. A first spacer **185** is formed between the gate structures **170** and the source regions **154***n,p*, and a second spacer **186** is formed between the gate structures **170** and the drain regions **140**, **142**. The spacers **185**, **186** can be made of SiN or SiC, for example.

FIG. **14** shows a third embodiment of the vertical GAA TFET that features etched source contacts **190** in place of dual damascene contacts **182**. The source contacts **190** differ from the dual damascene contacts **182** in that the source contacts **190** are formed by a subtractive etching process as opposed to forming and filling a trench, which is an additive process. Although either method can be used to form contacts to the source terminals of the GAA TFET, the front side source contacts **182** formed by the dual damascene process may offer lower contact resistance and a more flexible wire connection.

FIG. **15** shows steps in a method **200** of fabricating a vertical diode, according to one embodiment. The vertical diode can provide electrostatic discharge (ESD) protection for the vertical GAA TFET described above, to improve reliability. One advantage of the vertical diode is its small footprint, which is particularly useful in supporting GAA transistors used to form digital SRAM and DRAM arrays. The method **200** is further illustrated by FIGS. **16-19**, and described below. The ESD diode fabrication process can be performed at the same time as formation of the vertical GAA TFET and therefore the same reference numerals are used in the following description of the ESD diode formation, wherever possible.

At **202**, the silicon substrate **130** is implanted with dopants through openings in an implant hard mask **138** on a top side or surface **129** of the substrate **130**. In one embodiment, the implant hard mask **138** is a 10 nm-50 nm thick layer of SiO_2. An opening in the implant hard mask **138**, in the range of about 2 nm-200 nm can be patterned using an RIE process. Positive ions, such as boron, can then be implanted in the substrate to form a p-doped region, or P-well **142**, shown in FIG. **16**, having a dopant concentration of 1.0 E16 cm^{-3}-1.0 E 20 cm^{-3}. The P-well **142** is formed between a first portion **130-1** of the substrate **130** and a second portion **130-2** of the substrate **130**.

At **204**, an n-doped vertical nanowire **154** having a top end **157** and a bottom end **159**, shown in FIG. **16**, is formed by epitaxial growth from a top side or surface **141** of the p-doped region **142**. In one embodiment, the vertical nanowire **154** is made of indium arsenide (InAs) having a diameter anywhere in the range of about 2 nm-200 nm and a height anywhere in the range of about 8 nm-800 nm. Growth of the vertical nanowire **154** can be performed in a metal organic chemical vapor deposition (MOCVD) chamber using a trimethyl-indium (TMIn) source and a tertiary-butyl-arsine molar flow of 0.7 μMol/min-12.6 μMol/min, at a reactor pressure of 60 Torr, and a temperature between 400 C and 600 C. Negative doping of the vertical nanowire **154** can be achieved in-situ by injecting disilane gas (Si_2H_6) during the epitaxial growth process at Si_2H_6/TMIn ratios of 10^{-6}-10^{-2}. The junction of the bottom end **159** of the n-doped vertical nanowire **154** and the top side or surface **141** of the p-doped region **142** form a p-n diode **182***n*.

At **206**, the vertical nanowire **154** is encapsulated. In one embodiment, an encapsulant **174** is a layer of benzocyclobutene (BCB) that is spin-coated to cover the p-n diode **182***n*, and a CMP process is then used to planarize the encapsulant **174** to a target thickness above the vertical nanowire **154**.

At **208**, a front side contact is formed to the vertical nanowire **154** using a dual damascene process similar to that shown in FIGS. **10-11** and described above, in which a contact via and a metal line trench having a T-shaped profile are etched in the encapsulant **174**, and then the contact via and the metal line trench are filled with metal. The metal fill includes a liner **178** such as TiN, Ti/TiN, Ta, or TaN that surrounds a top portion **155** of the vertical nanowire **154**, and a bulk metal **180** such as W, Al, Cu, or Au that has a bottom portion or region **181** and a top portion or region **183**. A silicidation process may be performed is formed at the contact surfaces of the vertical nanowire **154** to further reduce contact resistance as described above. The bulk metal is then planarized to stop on the BCB layer.

At **210**, a backside contact **184** is made on a bottom side or surface **131** of the substrate **130** to a bottom side or surface **143** of the P-well **142**, similar to those shown in FIGS. **12-14** and described above.

FIG. **18** shows a pair of vertical diodes, including the p-n diode **182***n* described above, and a reciprocal p-n diode **182***p*. Whereas the p-n diode **182***n* includes a P-well and an n-doped vertical nanowire, the p-n diode **182***p* includes an N-well and a p-doped vertical nanowire. The two diodes are separated by an isolation region **132** that can be formed in the usual way, prior to doping the silicon substrate **130**. The diodes **182***p* and **182***n* have separate backside contacts **184***p* and **184***n*. Optional spacers **186** may be formed below the contact vias, prior to the encapsulation step **206**. The spacers **186** can be made of SiC or SiCNH, for example.

FIG. **19** shows an alternative contact **190** to the vertical p-n diode **182***n*. The alternative contact **190** is formed by recessing the encapsulant **174** down to a level below the top of the vertical nanowire **154**, and then performing metallization using a subtractive process instead of a dual damascene process. The subtractive process entails conformally

depositing a layer of metal and patterning and etching the metal, producing an inverted V-shaped profile. The alternative contact **190** is better suited to metal materials such as AlCu as opposed to Cu, which is difficult to etch. Following formation of the alternative contact **190**, a top ILD layer **192** is deposited and planarized to stop on the inverted V-shaped contact **190**.

FIG. **20** shows steps in a method **230** of fabricating an integrated horizontal p-n junction diode **222**, according to one embodiment shown in FIG. **21**.

At **232**, the silicon substrate **130** is implanted with an N-well **140** as described above in step **104**.

At **234**, the silicon substrate **130** is implanted with a P-well **142** adjacent to the N-well **140** as described above in step **104**, except that the P-well **142** partially overlaps the N-well **140** at **224**. The overlap can be accomplished via mask alignment or by using a tilted implantation process. The horizontal p-n junction diode **222** thus formed is useful in protecting GAA transistors used in analog and I/O circuits that sustain high currents and voltages.

At **236**, an insulating layer is formed, for example, the BCB encapsulant **158**, using a process similar to the one described above in step **110**.

At **238**, front side damascene contacts are made to the N-well **140** and the P-well **142**, using a process similar to the one described above in step **124**, wherein the contacts have T-shaped profiles.

At **240**, the backside contact **184** is formed to the silicon substrate **130**.

It will be appreciated that, although specific embodiments of the present disclosure are described herein for purposes of illustration, various modifications may be made without departing from the spirit and scope of the present disclosure. Accordingly, the present disclosure is not limited except as by the appended claims.

These and other changes can be made to the embodiments in light of the above-detailed description. In general, in the following claims, the terms used should not be construed to limit the claims to the specific embodiments disclosed in the specification and the claims, but should be construed to include all possible embodiments along with the full scope of equivalents to which such claims are entitled. Accordingly, the claims are not limited by the disclosure.

The various embodiments described above can be combined to provide further embodiments. All of the U.S. patents, U.S. patent application publications, U.S. patent applications, foreign patents, foreign patent applications and non-patent publications referred to in this specification and/or listed in the Application Data Sheet are incorporated herein by reference, in their entirety. Aspects of the embodiments can be modified, if necessary to employ concepts of the various patents, applications and publications to provide yet further embodiments.

The invention claimed is:

1. A device, comprising:
- a substrate having a first surface and a second surface opposite the first surface; and
- a diode including:
  - a first doped well in the substrate;
  - a second doped well in the substrate, the second doped well partially overlapping the first doped well in an overlapping region;
  - a first contact on the first surface of the substrate at the first doped well, the first contact having a first portion extending away from the first surface of the substrate in a first direction and a second portion extending in a second direction transverse to the first direction, the second portion being wider than the first portion;
  - a second contact on the first surface of the substrate at the second doped well, the second contact having a first portion extending away from the first surface of the substrate in the first direction; and
  - a third contact on the second surface of the substrate.

2. The device of claim **1**, wherein the second portion of the first contact has a width that is less than a width of the first doped well.

3. The device of claim **1**, wherein the second contact includes a second portion extending in the second direction.

4. The device of claim **3**, wherein the second portion of the second contact has a width that is less than a width of the second doped well.

5. The device of claim **3**, wherein the second portion of the first contact is spaced apart from the second portion of the second contact, and the overlapping region is aligned between the second portion of the first contact and the second portion of the second contact.

6. The device of claim **1**, further including an insulating layer on the first contact and the second contact.

7. The device of claim **6**, wherein the insulating layer is on the first surface of the substrate at the first doped well.

8. The device of claim **7**, wherein the insulating layer is on the first surface of the substrate at the second doped well.

9. A device, comprising:
- a substrate having a first surface and a second surface opposite the first surface in a direction;
- a first doped well extending from the first surface of the substrate toward the second surface of the substrate;
- a second doped well extending from the first surface of the substrate toward the second surface of the substrate, a portion of the second doped well overlapping a portion of the first doped well;
- a first damascene contact having a first portion at the first doped well that extends away from the first surface of the substrate in the direction;
- a second damascene contact having a first portion at the second doped well that extends away from the first surface of the substrate in the direction; and
- a third contact on the second surface of the substrate.

10. The device of claim **9**, further including an insulating layer on the first damascene contact and the second damascene contact.

11. The device of claim **10**, wherein the insulating layer is on the first surface of the substrate at the first doped well and the second doped well.

12. The device of claim **9**, wherein the first damascene contact and the second damascene contact are T-shaped.

13. A method, comprising:
- forming a first doped well in a substrate having a first surface and a second surface opposite the first surface;
- forming a second doped well in the substrate, the second doped well partially overlapping the first doped well;
- forming a first damascene contact on the first surface of the substrate at the first doped well, the first damascene contact having a first portion extending away from the first surface of the substrate in a first direction;
- forming a second damascene contact on the first surface of the substrate at the second doped well, the second damascene contact having a first portion extending away from the first surface of the substrate in the first direction; and
- forming a third contact on the second surface of the substrate.

14. The method of claim 13, further including forming an insulating layer on the first surface of the substrate.

15. The method of claim 14, wherein the forming the first damascene contact includes:

forming a first recess and exposing a first portion of the first surface of the substrate at the first well by removing a first portion of the insulating layer; and

forming the first damascene contact in the first recess.

16. The method of claim 15, wherein forming the second damascene contact includes:

forming a second recess and exposing a second portion of the first surface of the substrate at the second well by removing a second portion of the insulating layer; and

forming the second damascene contact in the second recess.

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